FOIA Number: 2008-1524-F

FOIA MARKER

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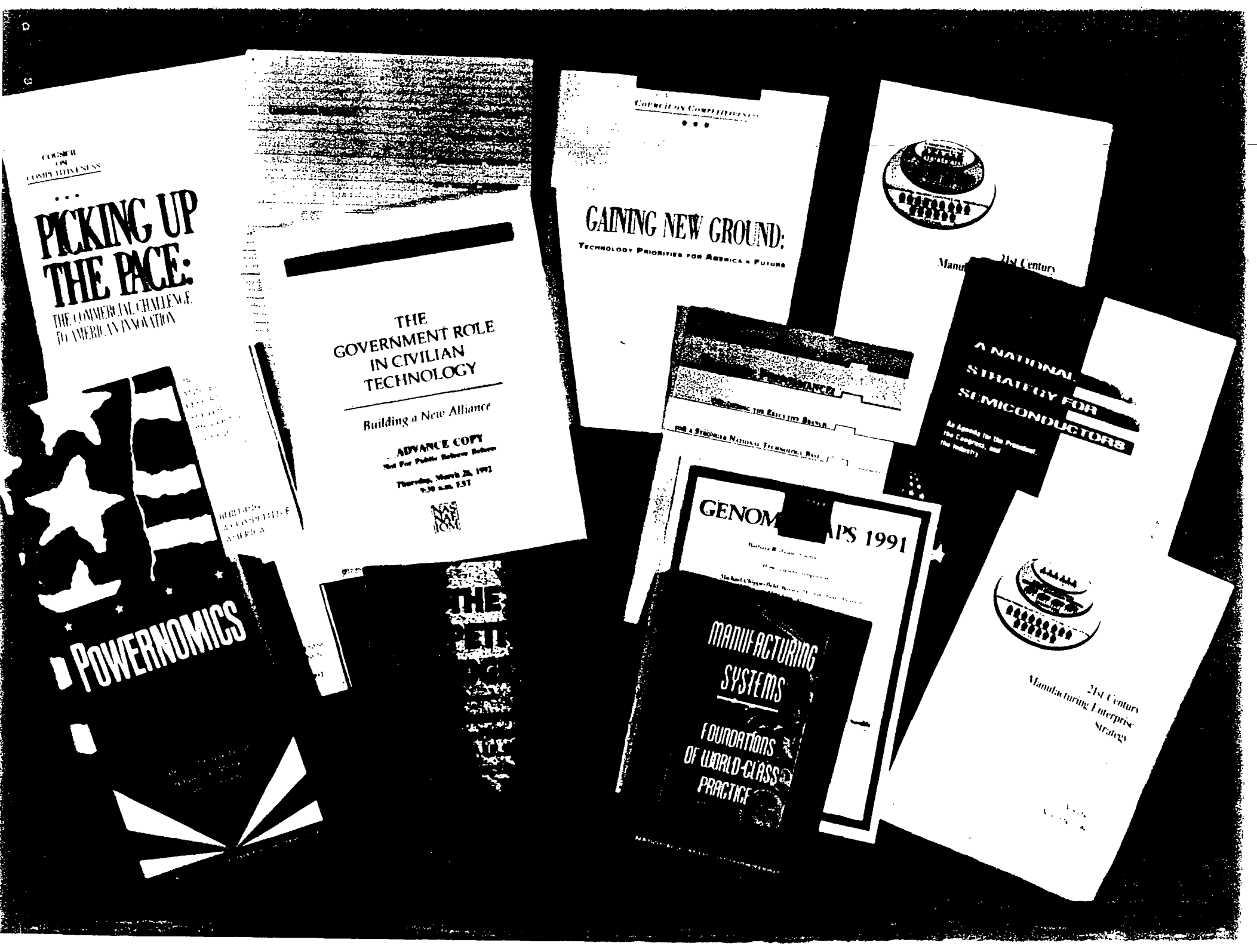
Sematech Inc [3]

Stack:	Row:	Section:	Shelf:	Position:
S	66	4	5	1

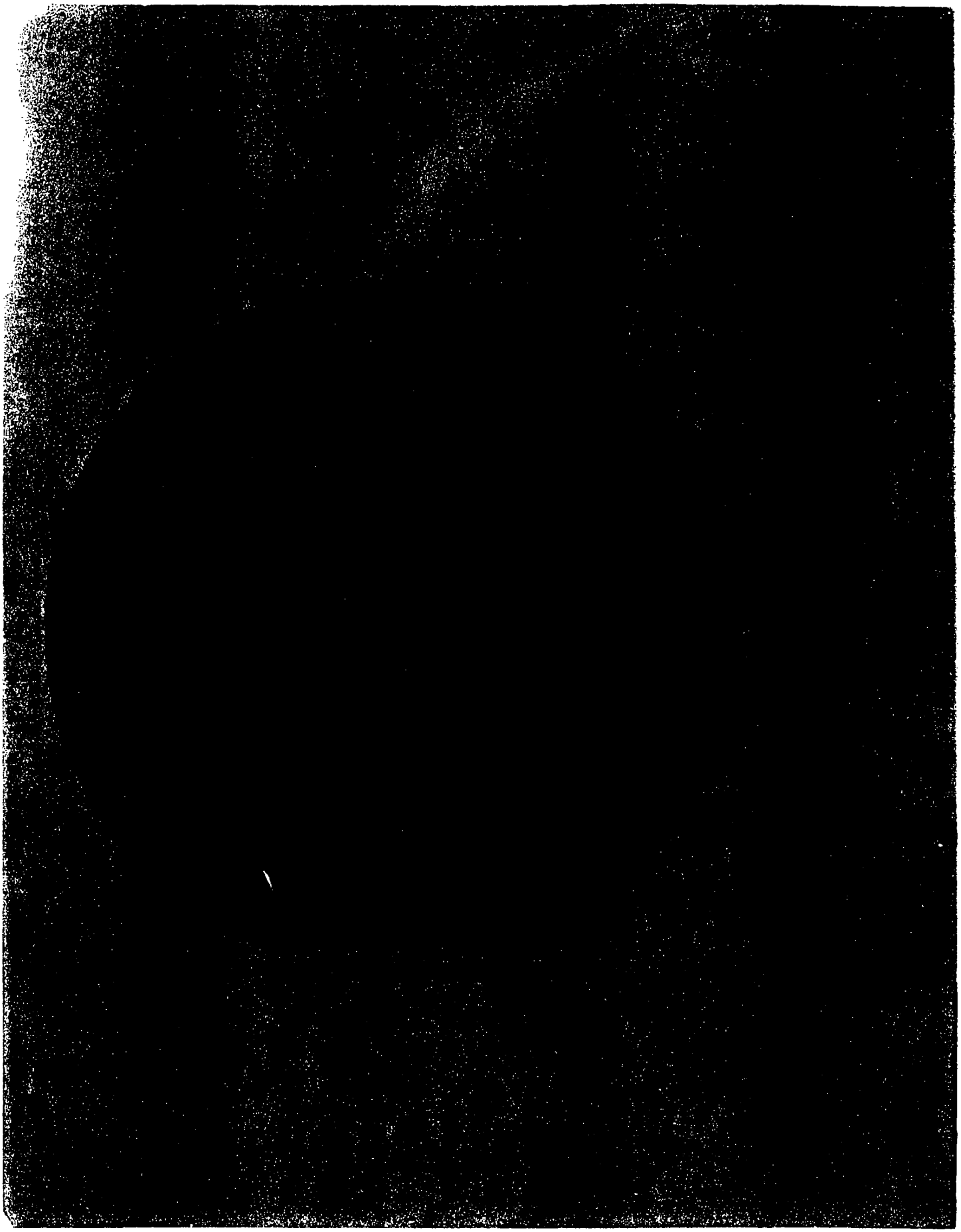
SEMATECH

Skip —
copy of
Sematech viewgraphs
from Bill Spencer —
[illegible]


COUNCIL ON COMPETITIVENESS
PICKING UP THE PACE:
THE COMMERCIAL CHALLENGE TO AMERICAN INNOVATION
POWERNOMICS
THE GOVERNMENT ROLE IN CIVILIAN TECHNOLOGY
Building a New Alliance
ADVANCE COPY
GAINING NEW GROUND:
TECHNOLOGY PRIORITIES FOR AMERICA'S FUTURE
A NATIONAL STRATEGY FOR SEMICONDUCTORS
GENOM APS 1991
MANUFACTURING SYSTEMS
FOUNDATIONS OF WORLD-CLASS PRACTICE
21st Century Manufacturing Enterprise Strategy

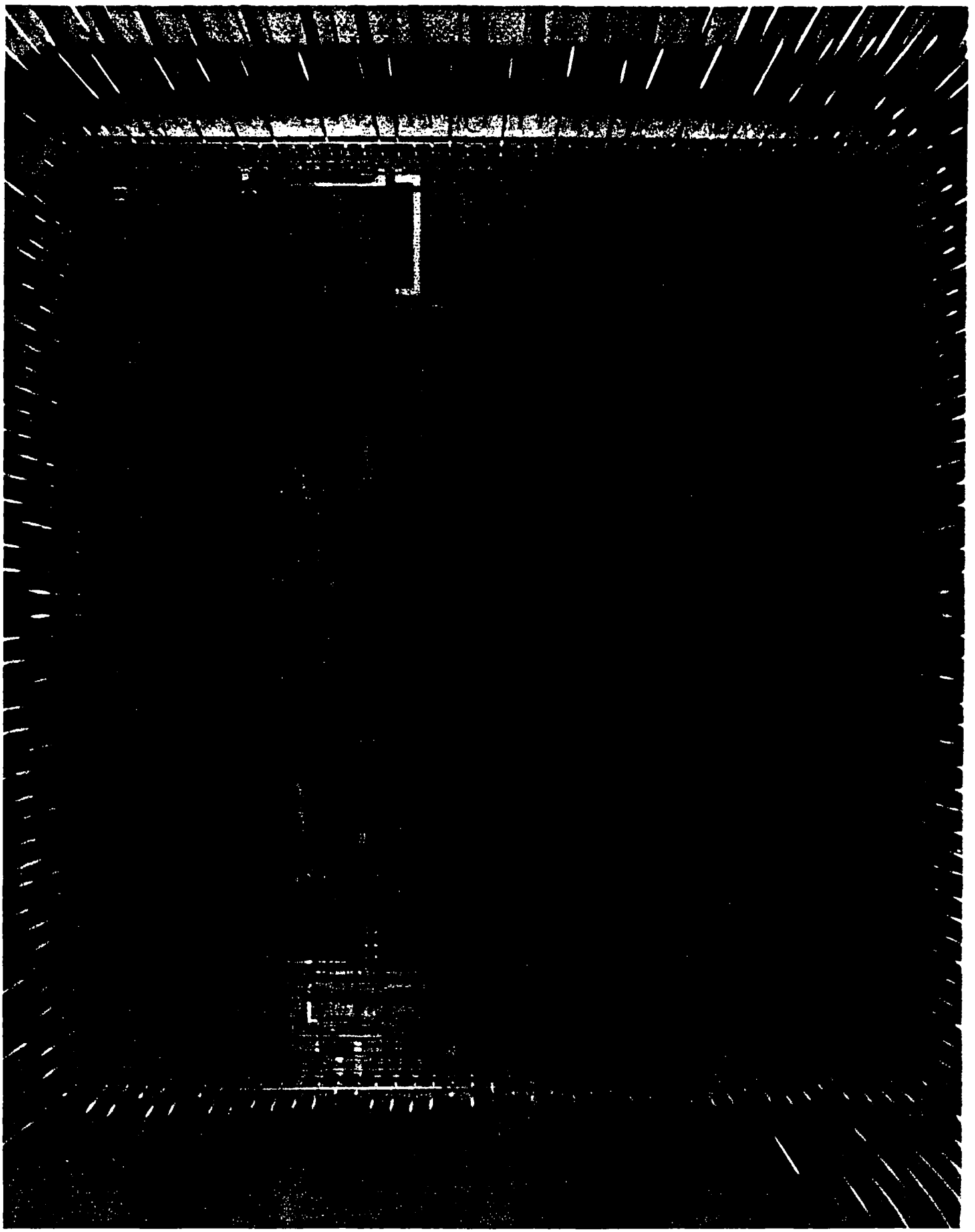
POLAROID

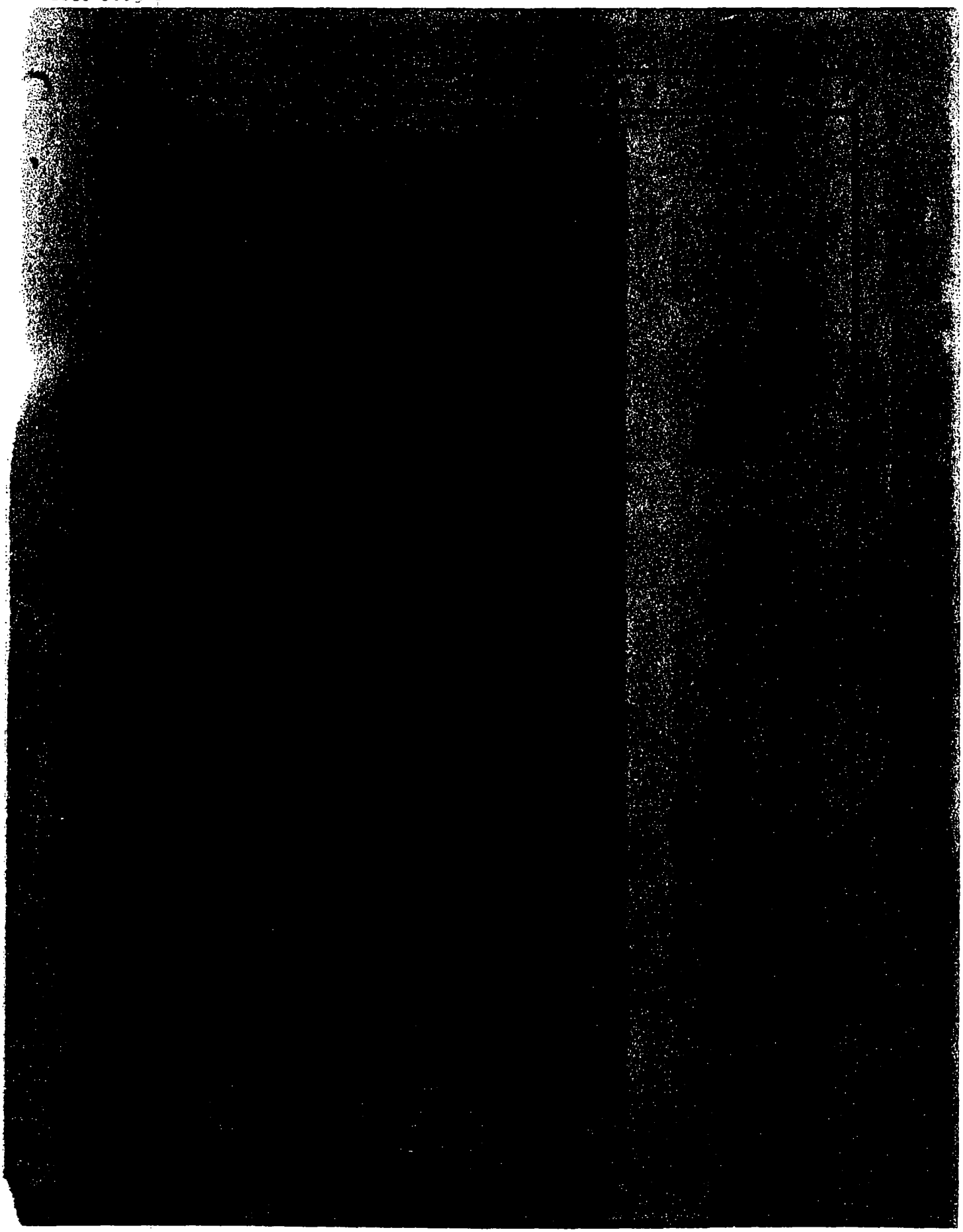
B173 0333 C



POLAROID

D005 2745 P





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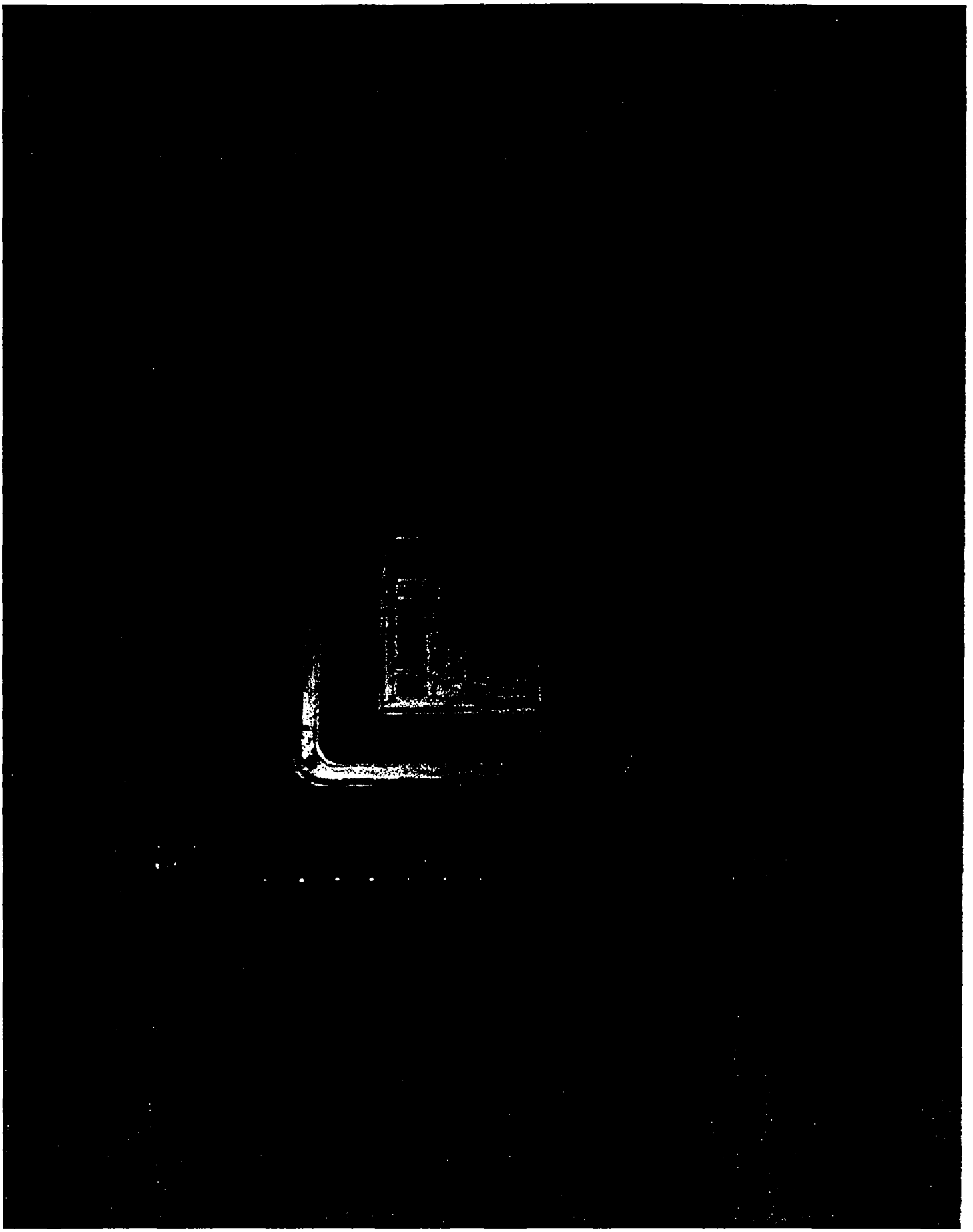
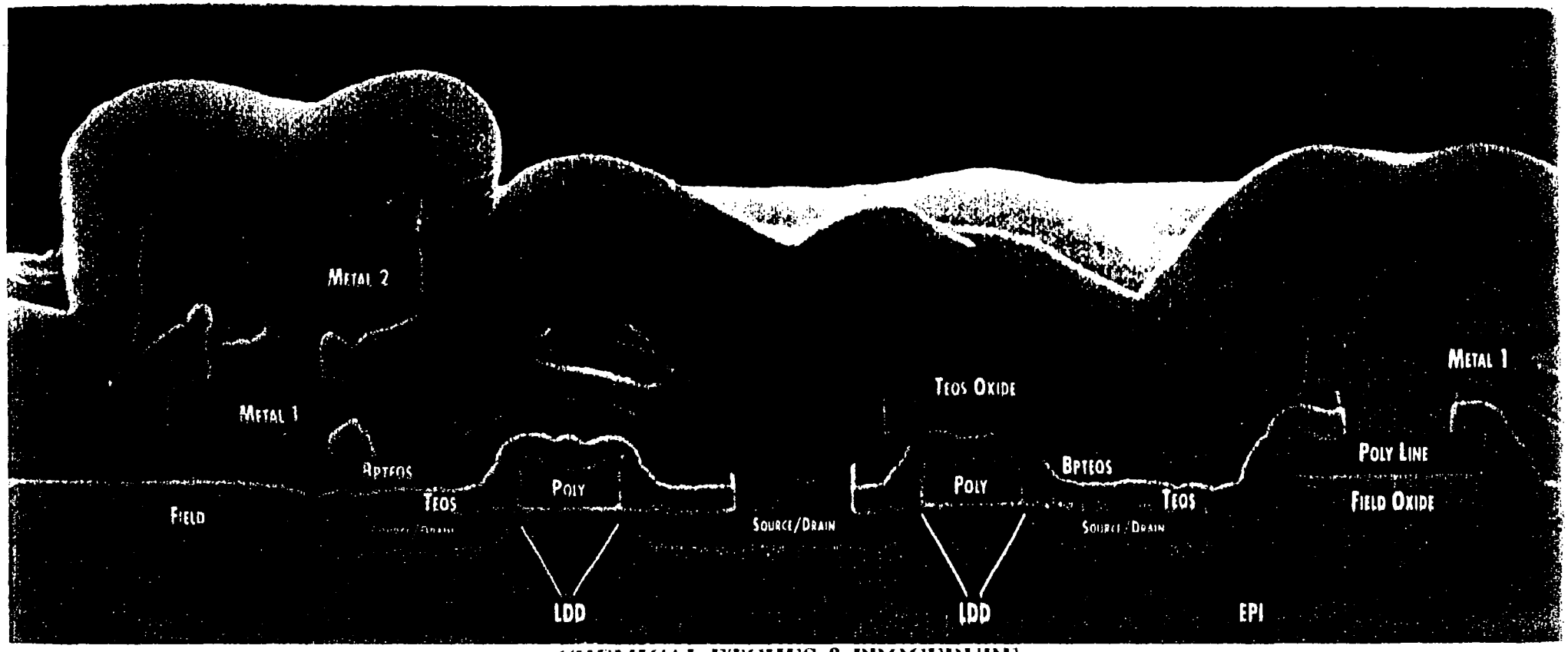


Cross Section of a Finished Device



CHEMICAL ETCHES & PROCEDURE

ABBREVIATIONS:

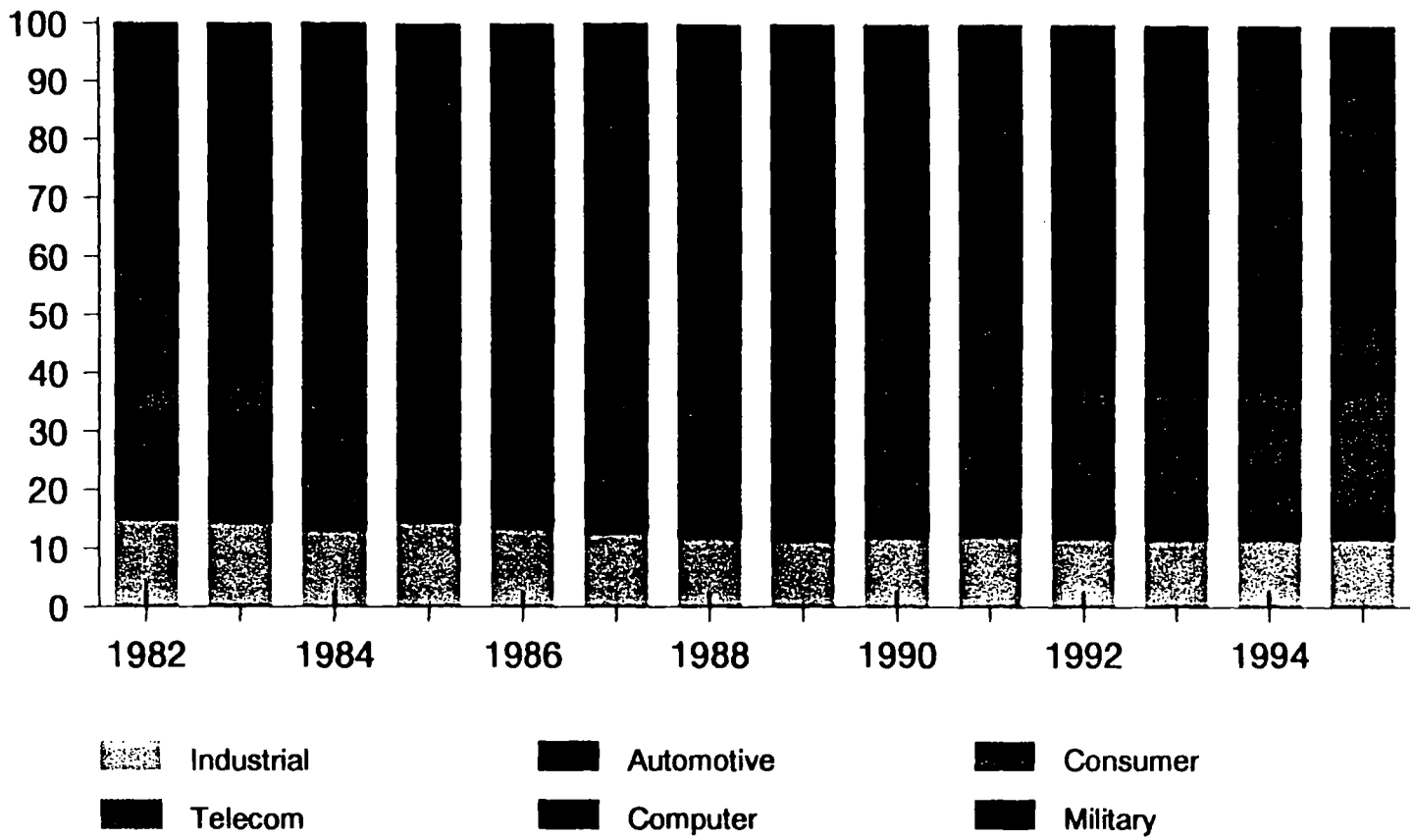
- NH_4F AMMONIUM FLUORIDE
- DIH_2O DEIONIZED WATER
- HAC ACETIC ACID, GLACIAL
- HNO_3 NITRIC ACID
- HF HYDROFLUORIC ACID

1. S/O (Silicon oxide) = 1 min.
   - 62.5 ml NH_4F (40%)
   - 207.0 ml DIH_2O
   - 250.0 ml HAC (99.7%)

2. 10 : 1 : 1 / ~3 sec.
   - 10 ml HNO_3 (70%)
   - 1 ml HF (49%)
   - 7 ml HAC (99.7%)

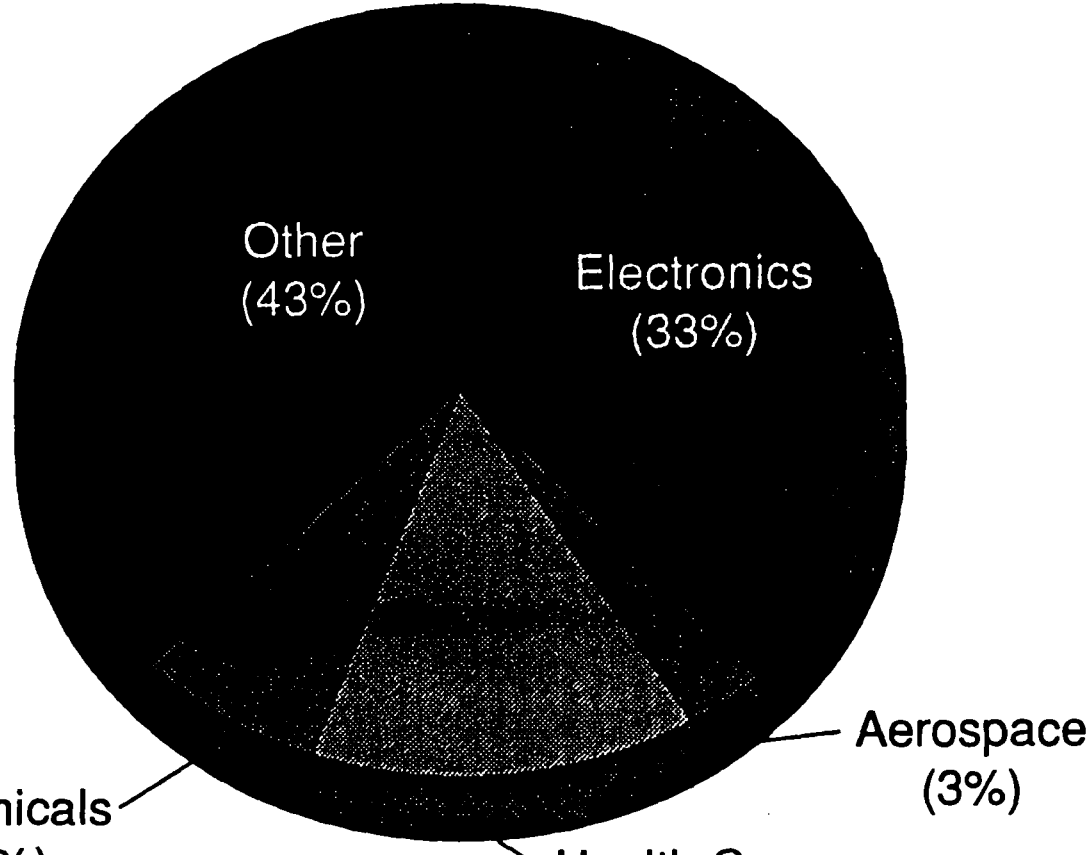
3. Diode Etch - 1 sec.
   - 8.5 ml HNO_3 (70%)
   - 1.5 ml HF (49%)
   - 7.0 ml HAC (99.7%)

END-USE MARKET WORLDWIDE - IC
PERCENT



SEMATECH

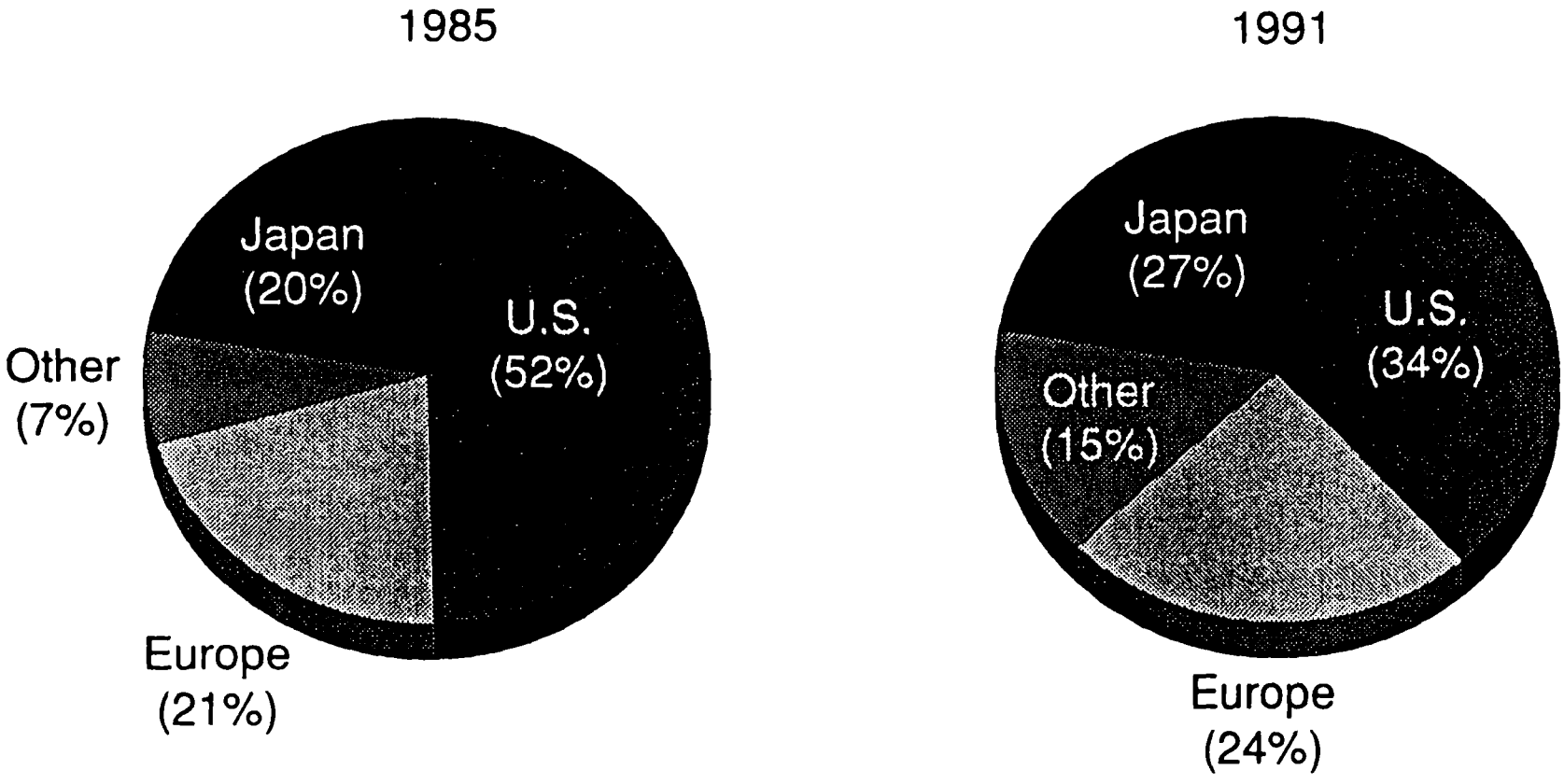
INDUSTRY SECTOR R&D SPENDING AS A PERCENT OF ALL INDUSTRIAL 1991 R&D ($78B)



Source: Computer Systems Policy Project and AEA

SEMATECH

AMERICAN ELECTRONICS: DECLINING GLOBAL MARKET SHARE



Source: AEA, based on U.S. Commerce Department data

SEMATECH

SEMATECH: INCORPORATED ON AUGUST 7, 1987

MISSION:

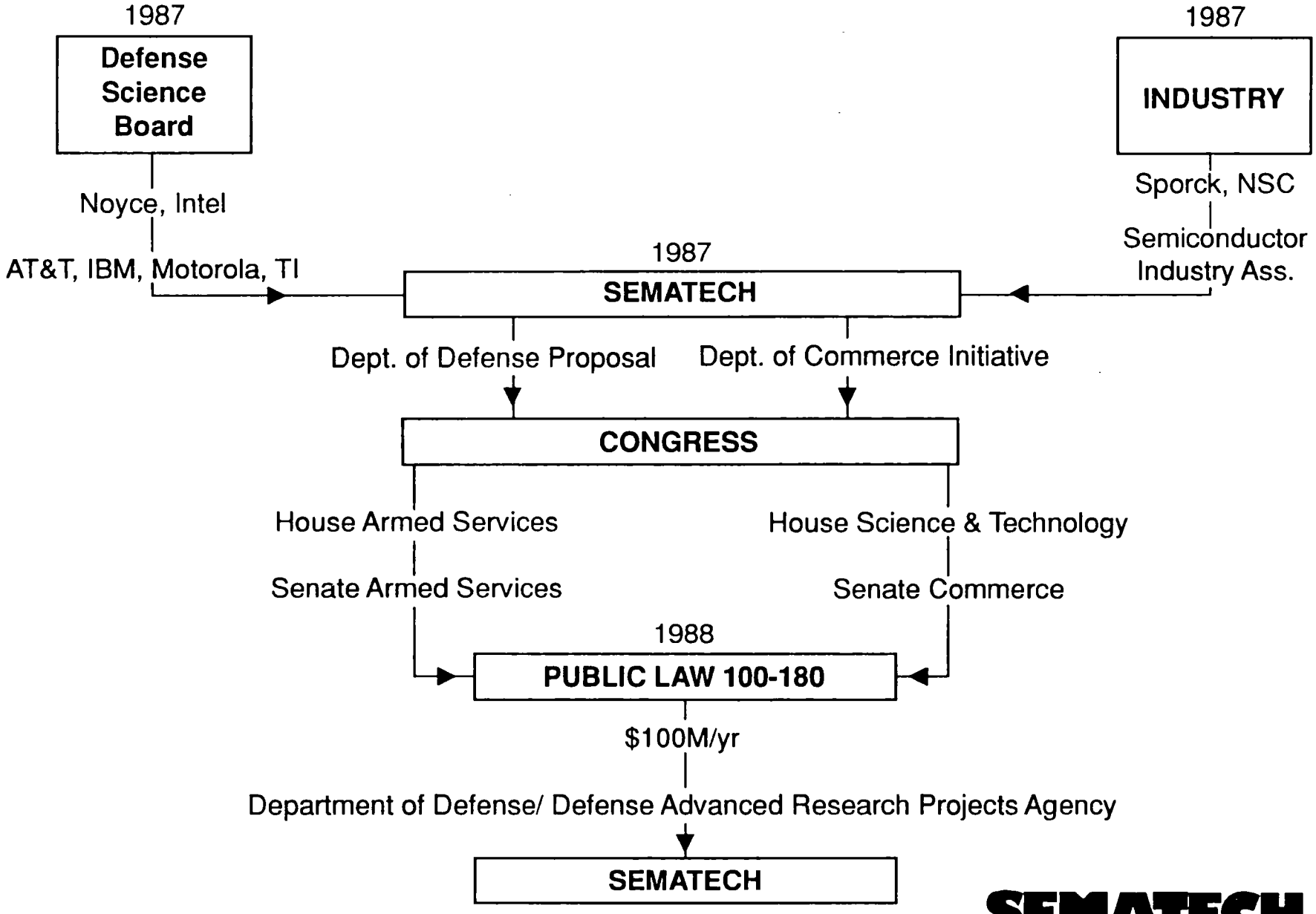
To provide the U.S. semiconductor industry the domestic capability for world leadership in manufacturing

MEMBERS:

AMD
AT&T
DARPA
DIGITAL EQUIPMENT
HARRIS
HEWLETT-PACKARD
IBM
INTEL
LSI LOGIC
MICRON
MOTOROLA
NCR
NATIONAL SEMICONDUCTOR
ROCKWELL
TEXAS INSTRUMENTS

SEMATECH

THE GENESIS OF SEMATECH



SEMATECH

SEMATECH MILESTONES

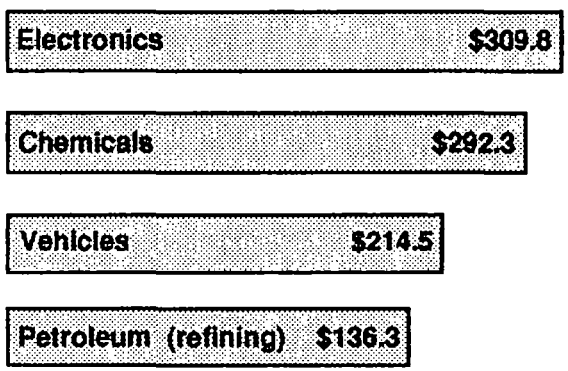
8/87	SEMATECH Incorporated
11/88	Facilities Dedicated
3/89	First Phase 1 Silicon Yielded
3/89	First Joint Development Contract Awarded
8/90	Phase 2 Product on American Equipment
10/90	William J. Spencer Announced as CEO
3/92	200 mm Completed
4/92	U.S. Equipment Supplier Market Share Gains Reported
4/92	First SEMATECH Spinoff Announced
11/92	U.S. Semiconductor Market Share Gains Reported
12/92	Phase 3 Product on American Equipment

SEMATECH

HOW ELECTRONICS INDUSTRY STACKS UP

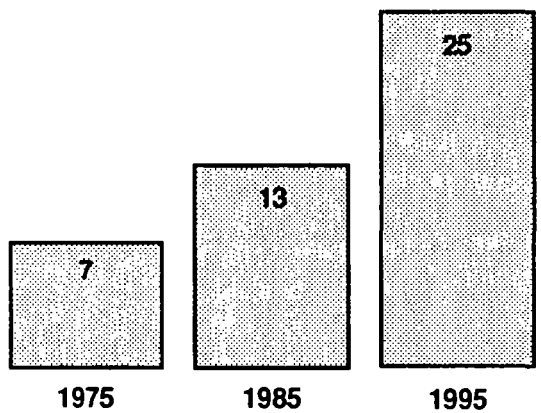
Electronics is the largest basic industry in the United States ...

Shipments in billions for 1991.



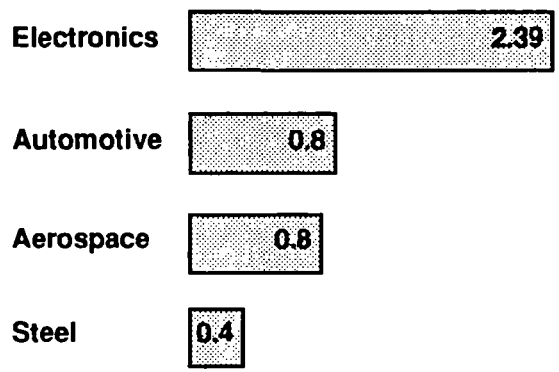
...and electronics is the fastest growing manufacturing industry...

Electronics as a % of total of U.S. manufacturing output.



...and is the largest industrial employer.

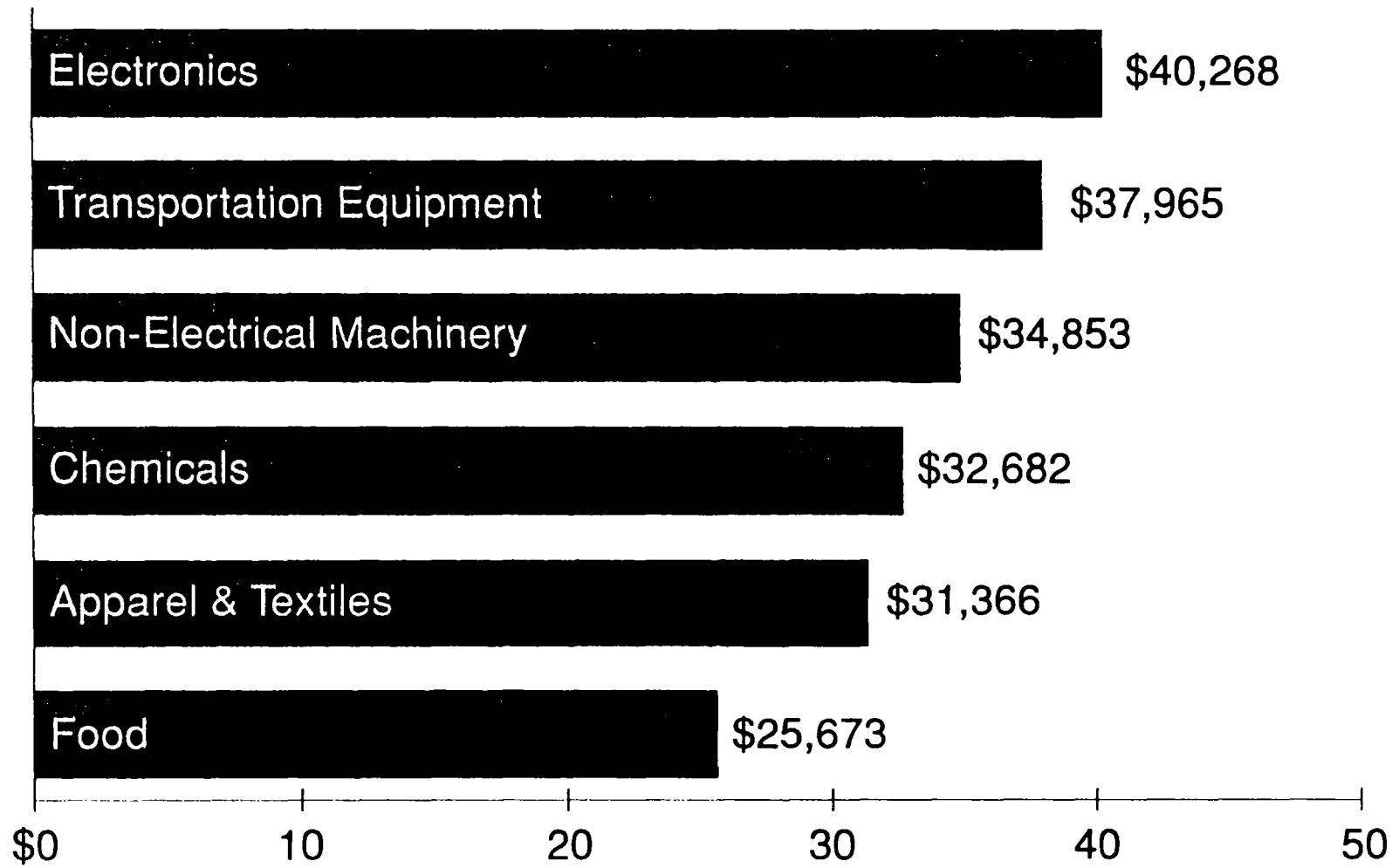
Number of jobs, in millions, in 1991.



Sources: U.S. Commerce Department, American Electronics Association, *The Dallas Morning News*

SEMATECH

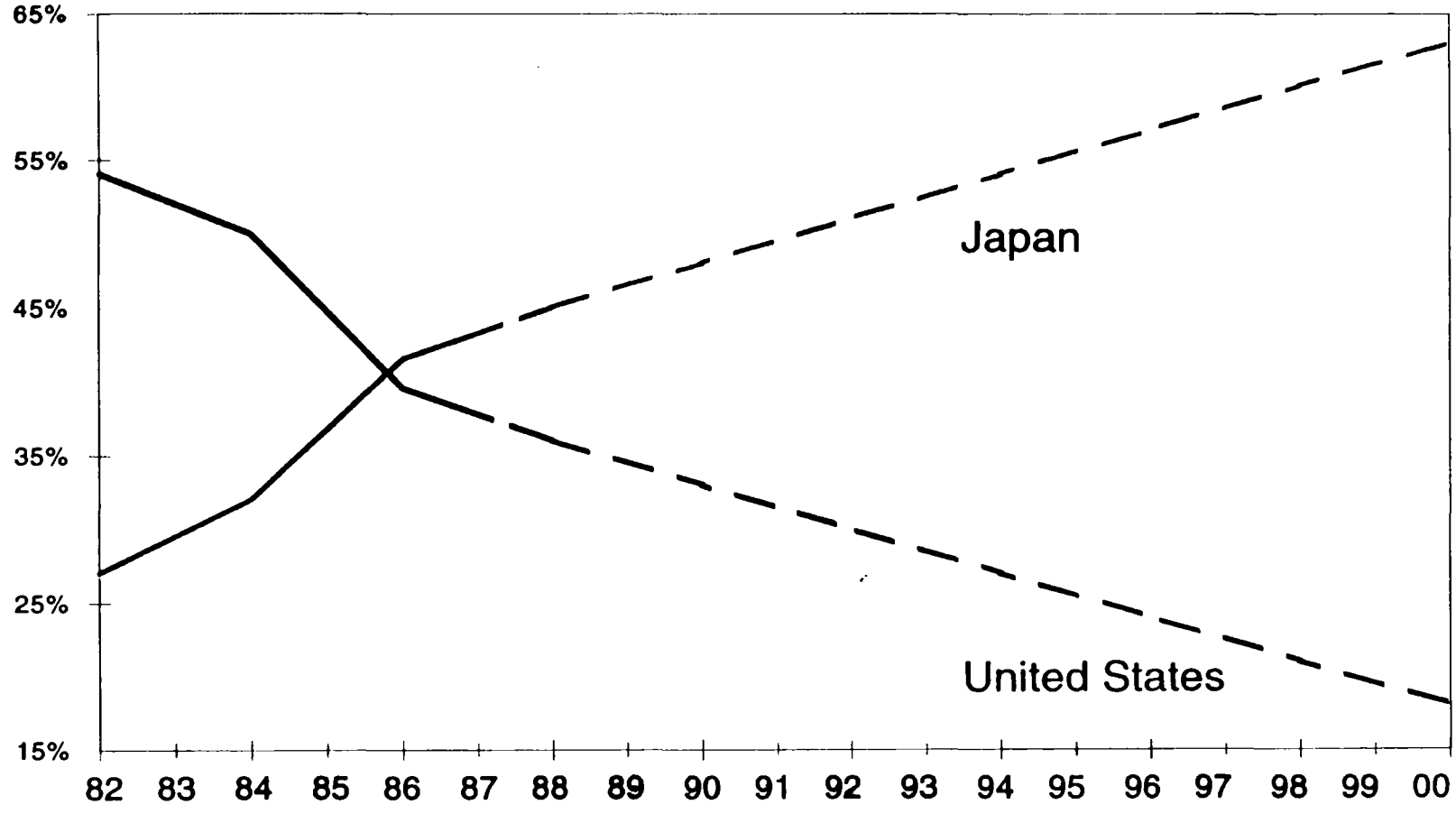
HIGH-WAGE INDUSTRIES
PAYROLL PER EMPLOYEE, CALIFORNIA



Source: AEA, with data from U.S. Bureau of the Census

SEMATECH

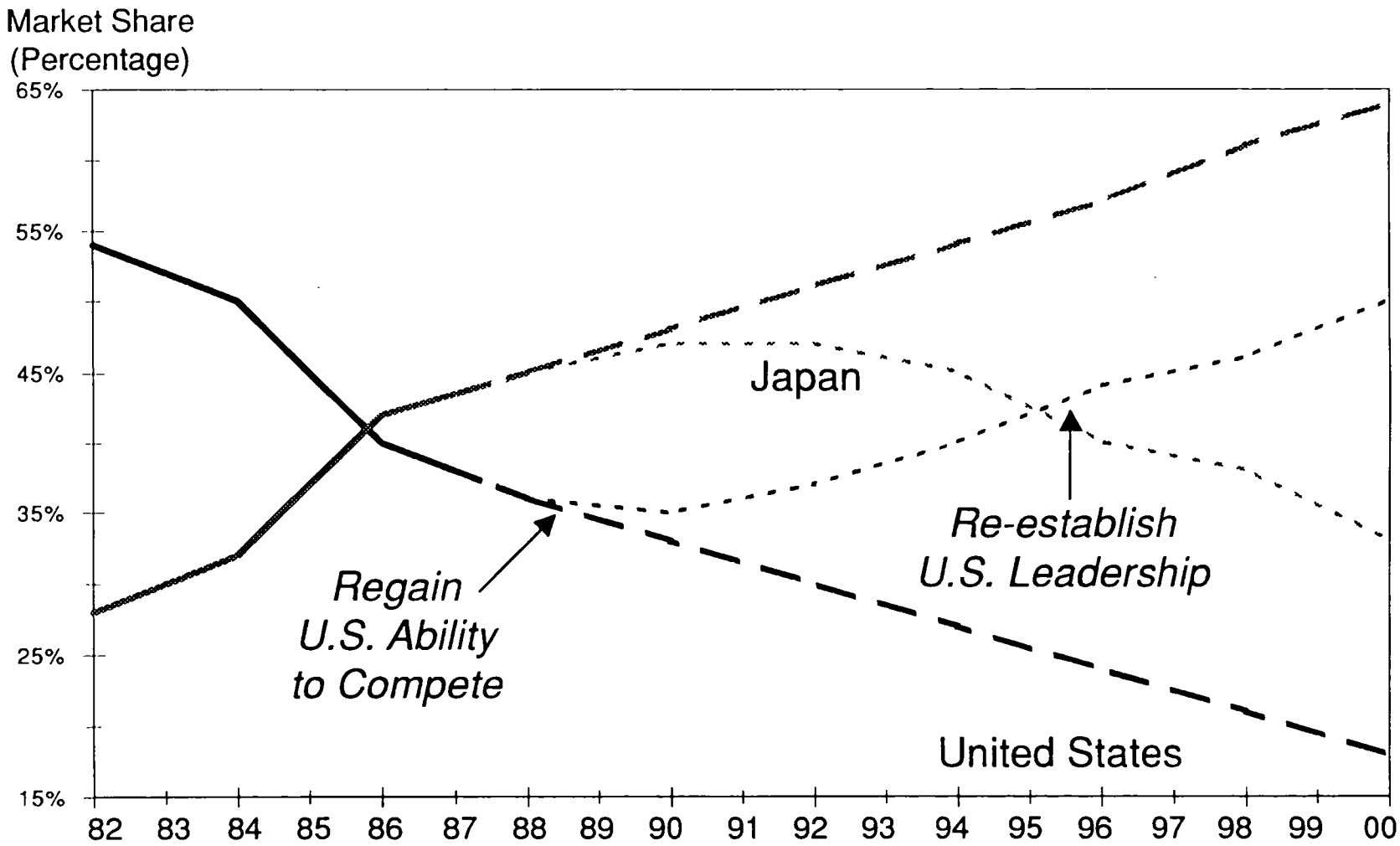
1987 PROJECTION OF U.S. & JAPANESE MARKET SHARES FOR WORLDWIDE SEMICONDUCTOR INDUSTRY



Source: SIA, February 1987 projections based on extrapolation of trends up to 1987

SEMATECH

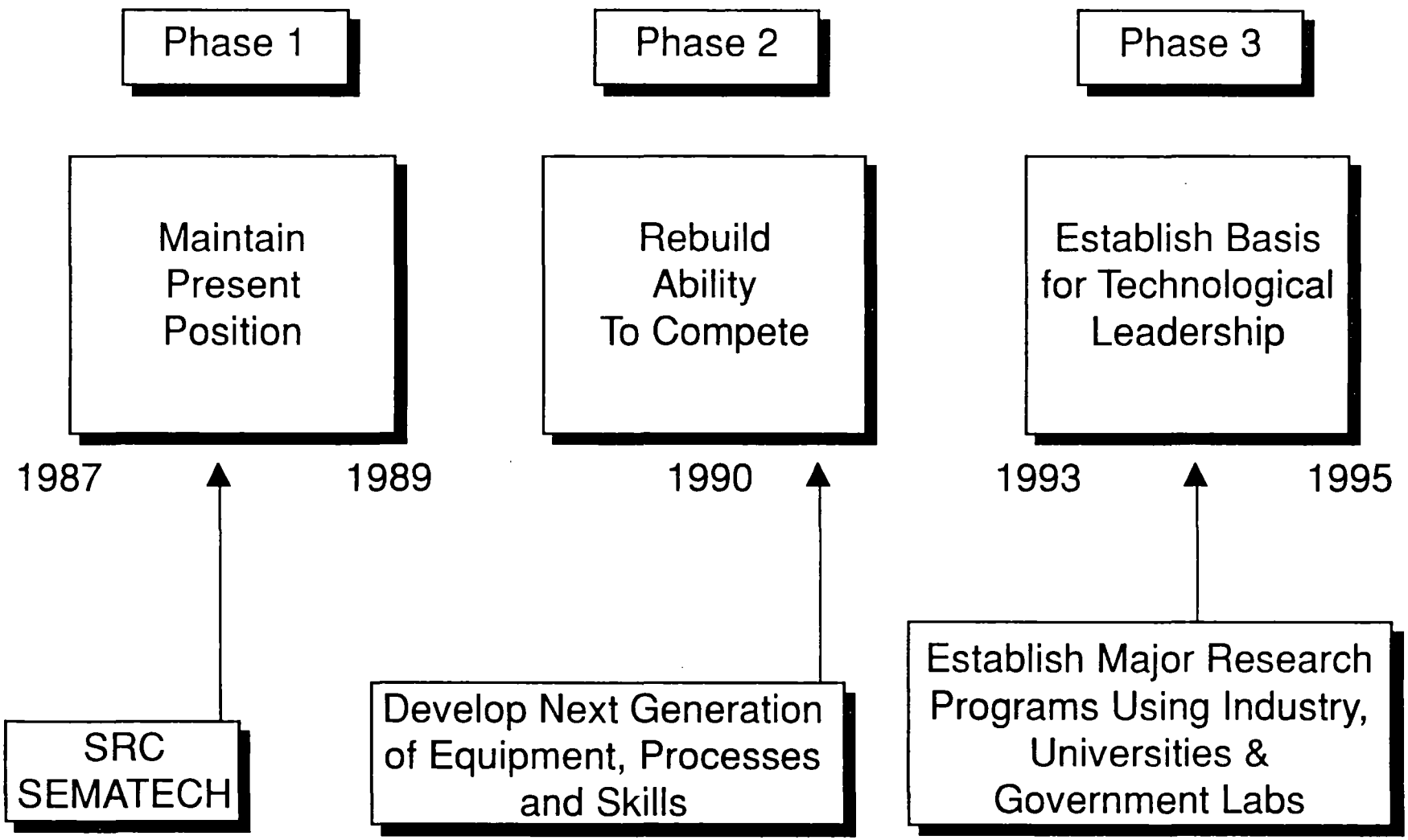
WINNING STRATEGY



Source: SIA, February 1987 projections

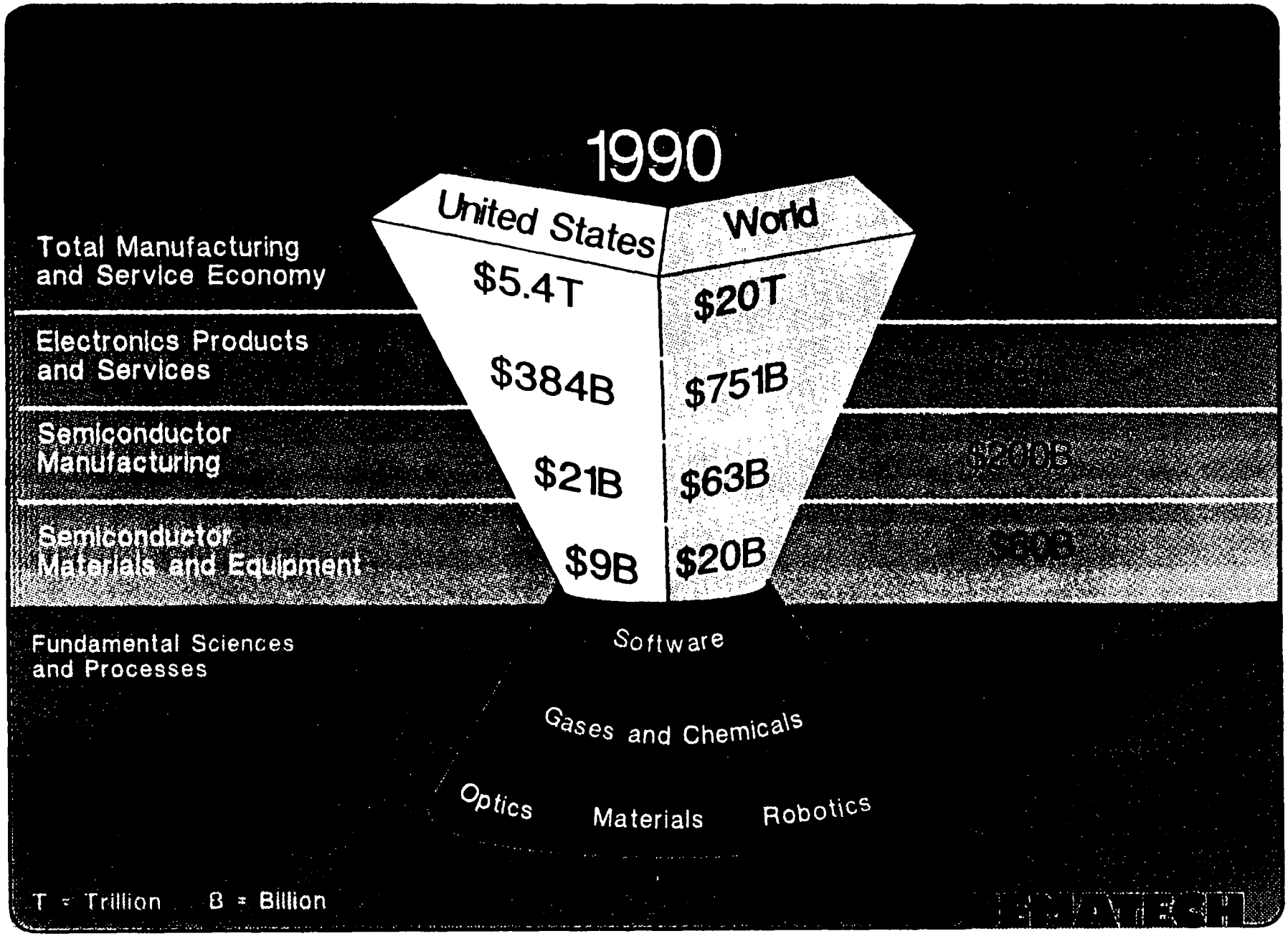
SEMATECH

REBUILDING TECHNOLOGICAL LEADERSHIP

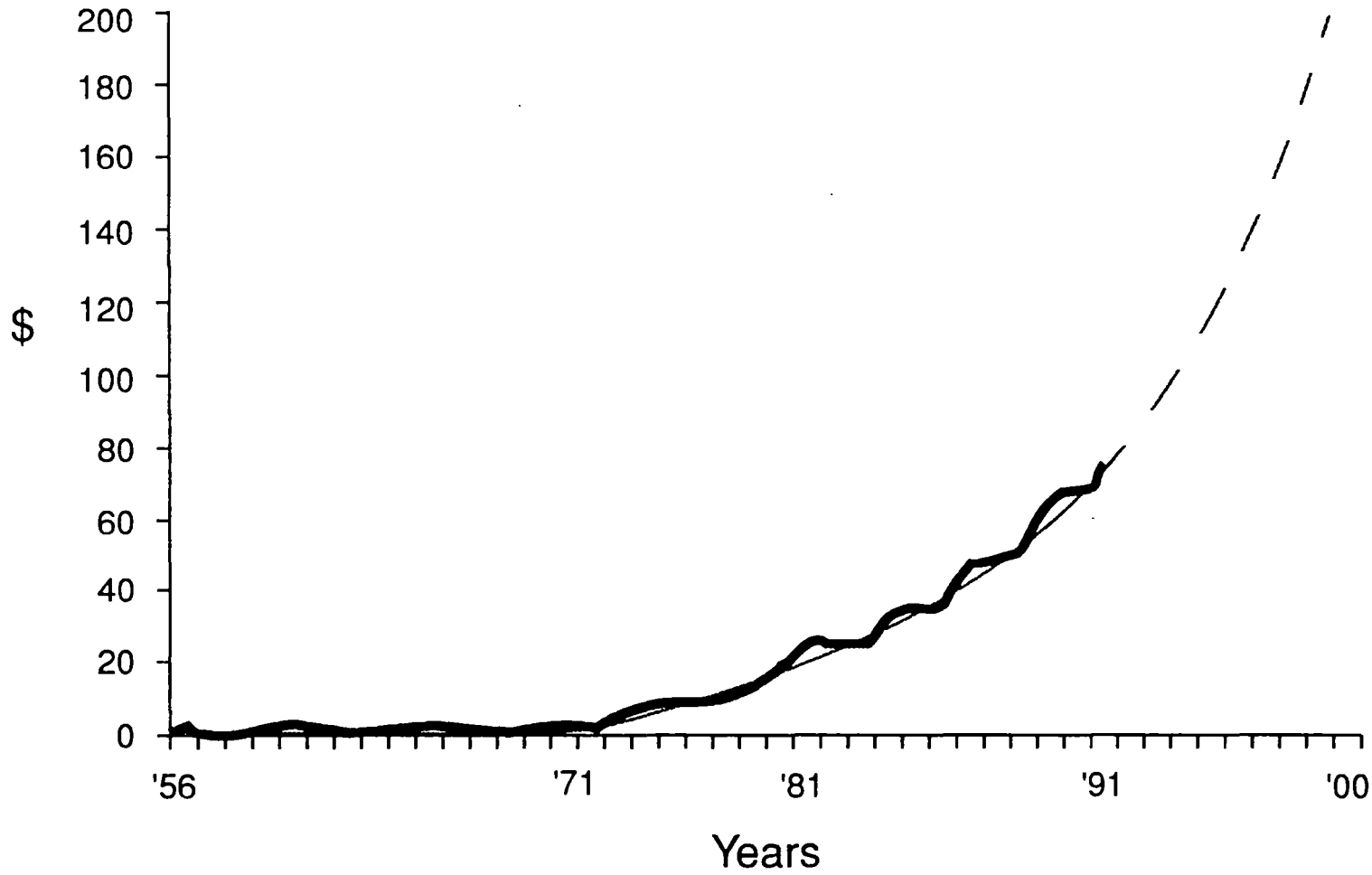


Source: SIA, February 1987

SEMATECH


1990
United States
World
Total Manufacturing and Service Economy
$5.4T
$20T
Electronics Products and Services
$384B
$751B
Semiconductor Manufacturing
$21B
$63B
Semiconductor Materials and Equipment
$9B
$20B
Fundamental Sciences and Processes
Software
Gases and Chemicals
Optics
Materials
Robotics
T = Trillion
B = Billion

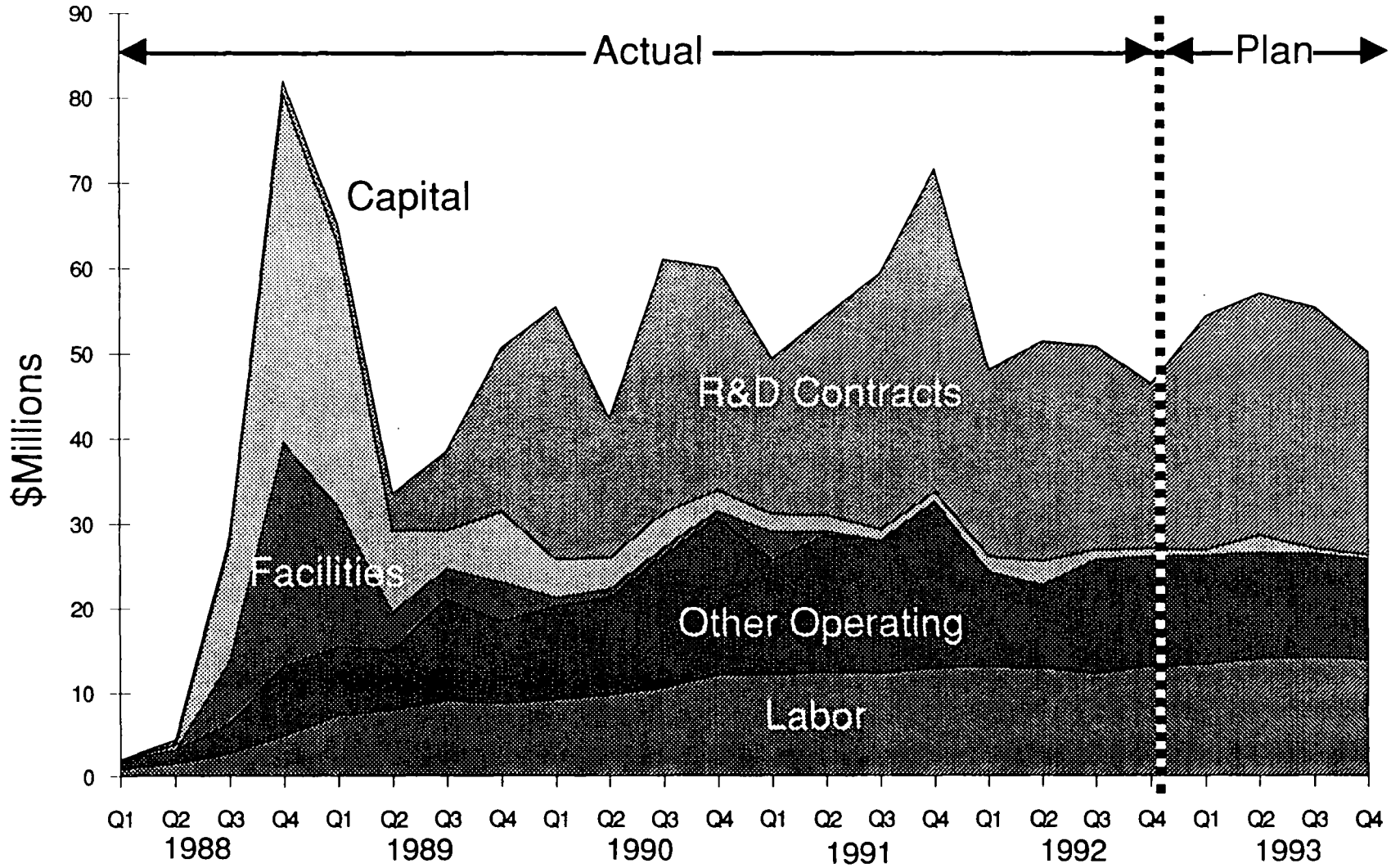
WORLDWIDE SEMICONDUCTOR CONSUMPTION
(DOLLARS IN BILLIONS)



Source: Dataquest, Intel

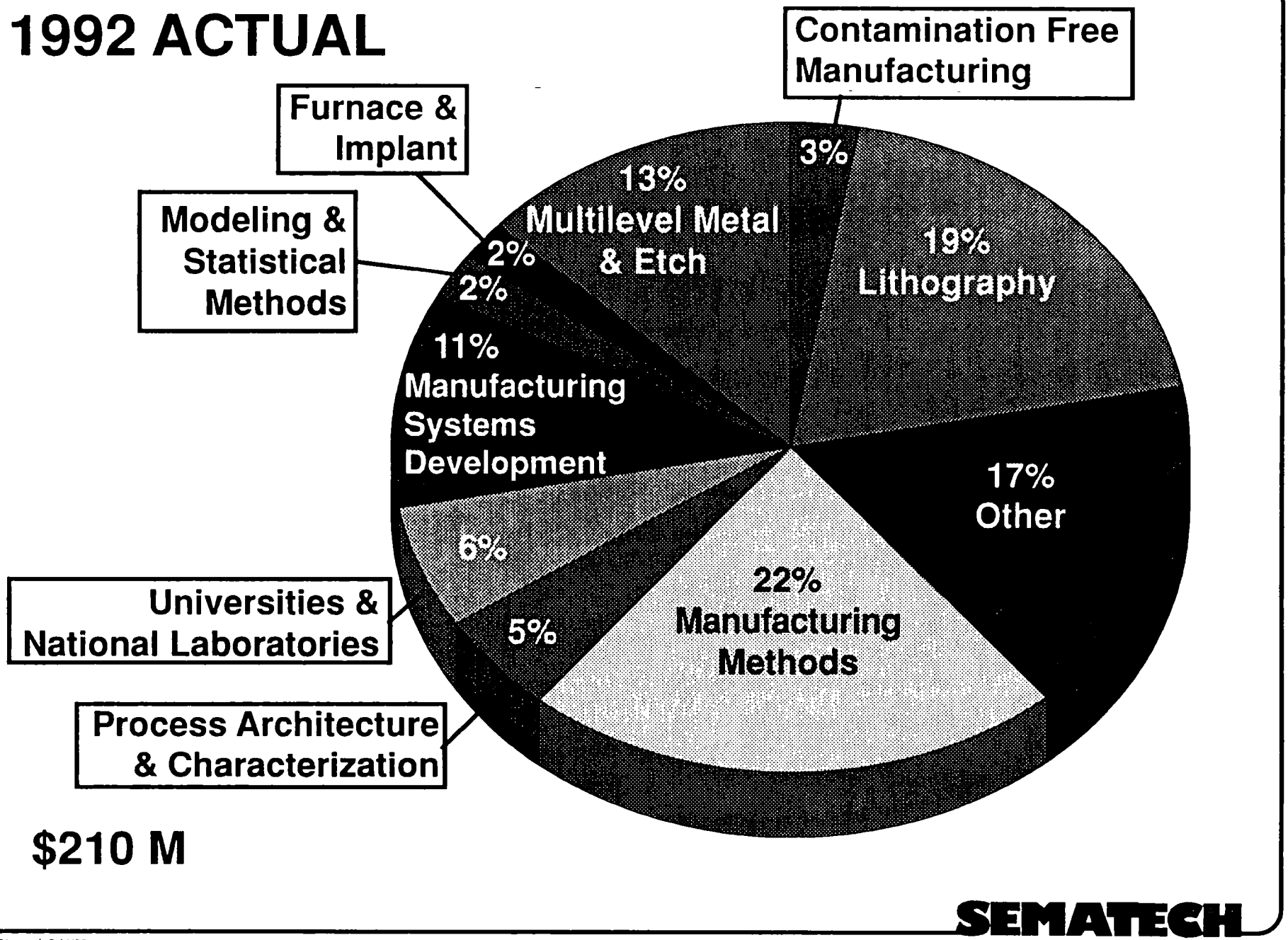
SEMATECH

EXPENDITURE PATTERN
(PER QUARTER)



SEMATECH

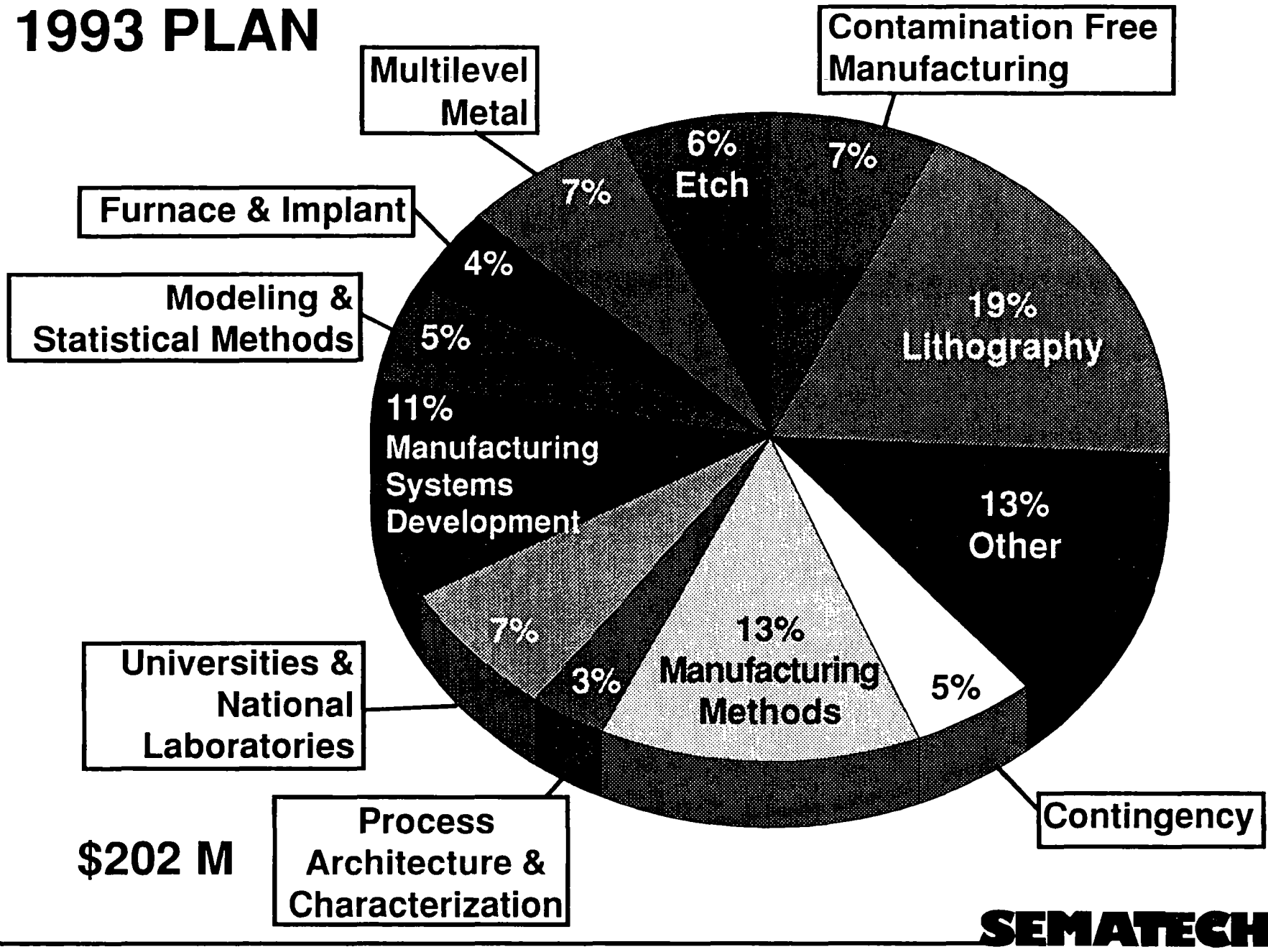
1992 ACTUAL



$210 M

SEMATECH

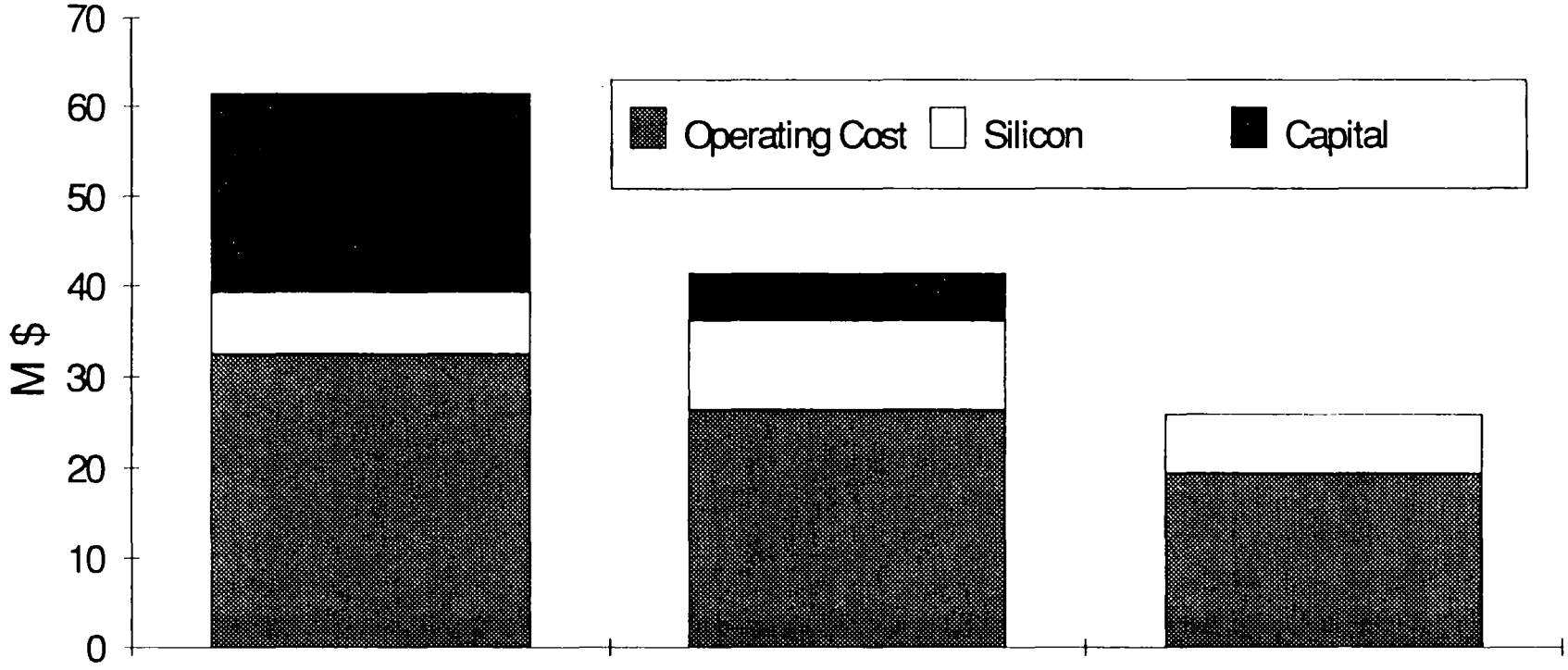
1993 PLAN



$202 M

SEMATECH

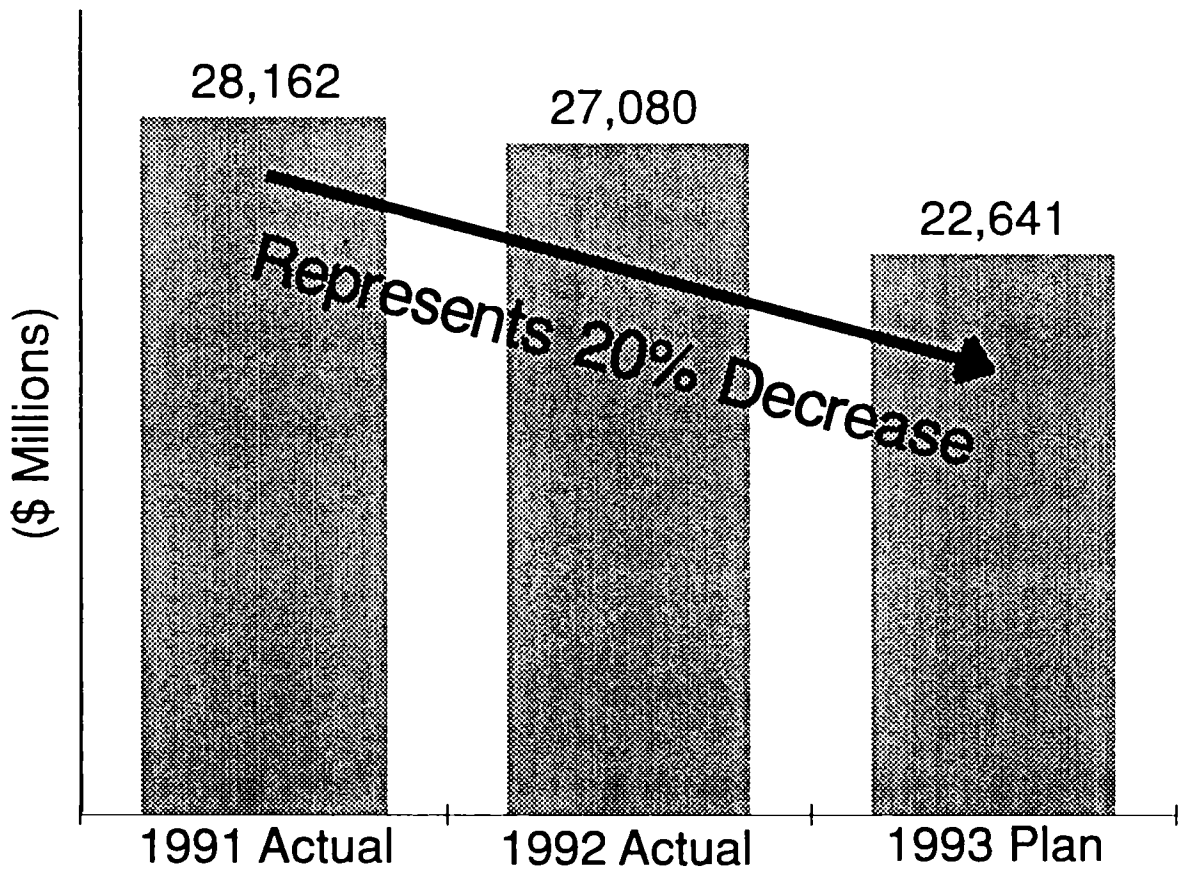
MANUFACTURING OPERATIONS
Fab Expenditures



	1991	1992	1993
Operating Cost	32.4	26.3	19.4
Silicon	6.8	9.8	6.5
Capital	22.2	5.2	0

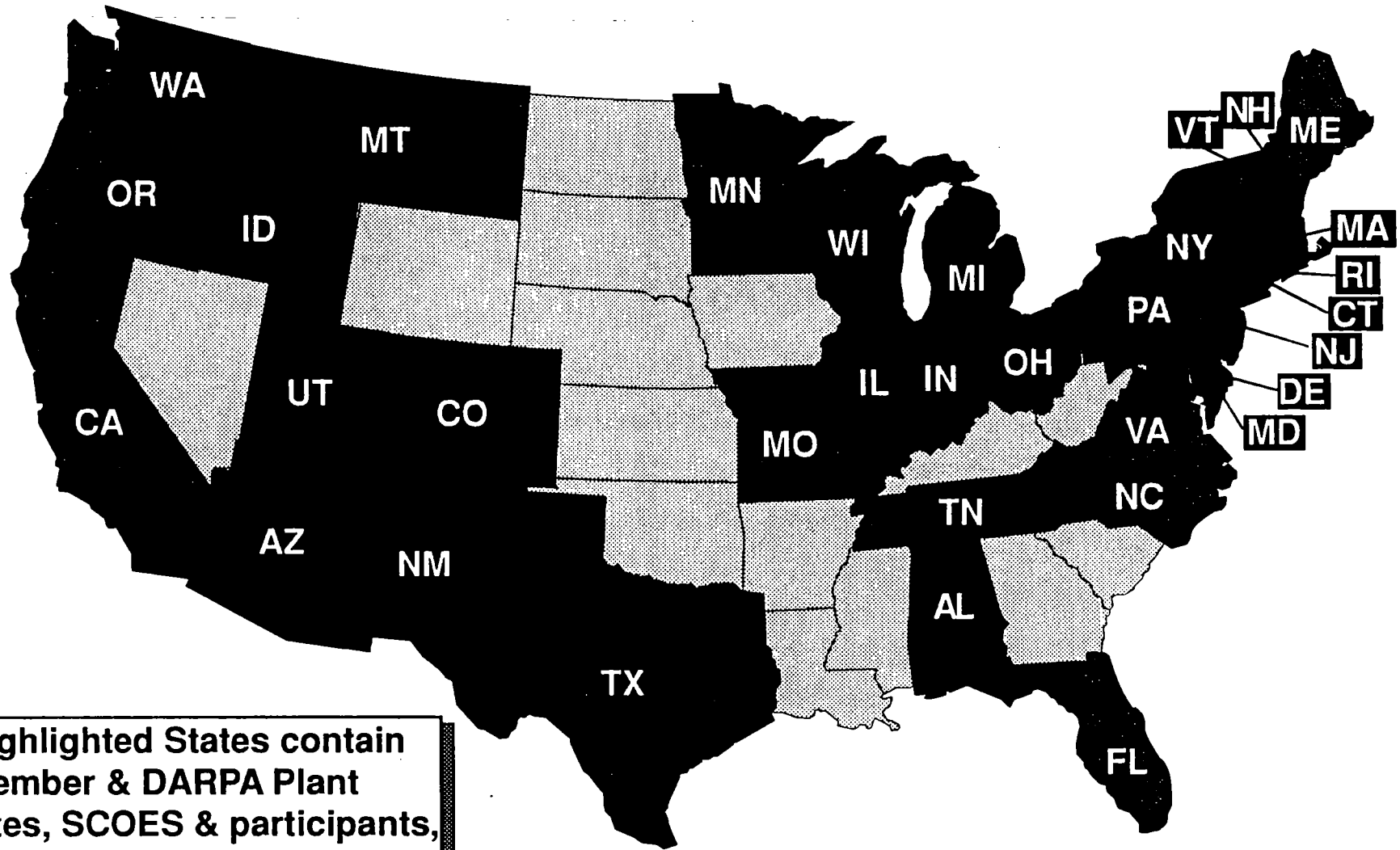
SEMATECH

SUPPORT COST REDUCTIONS
TOTAL CAO



SEMATECH

SEMATECH: A NATIONAL MISSION WITH A NATIONAL SCOPE



Highlighted States contain Member & DARPA Plant sites, SCOES & participants, JDP/EIP Projects/suppliers, National Labs, and/or SEMI/SEMATECH Members

SEMATECH

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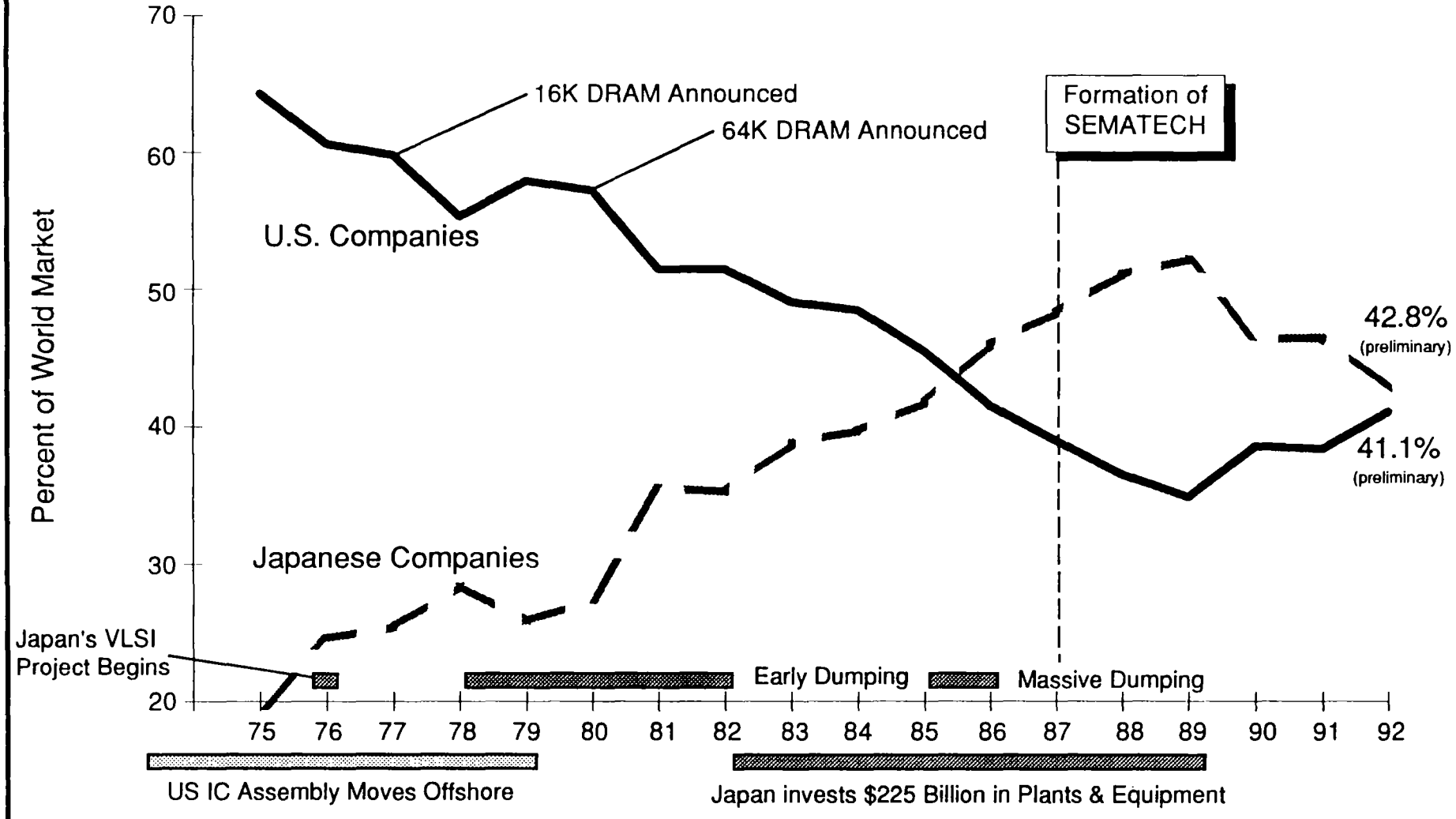
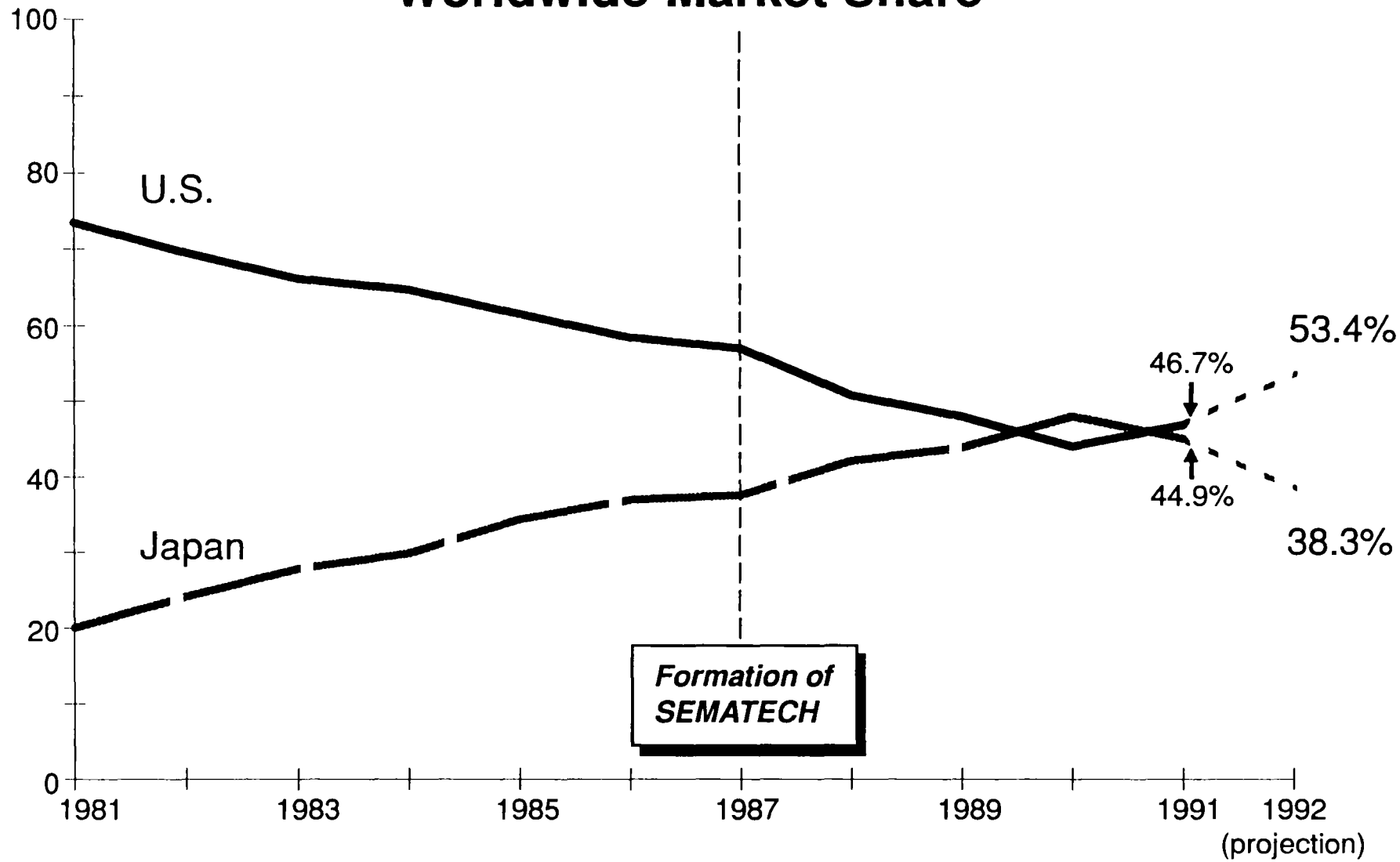
WORLD SEMICONDUCTOR MARKET SHARE



Source: Dataquest,
Prudential - Bache

SEMATECH

SEMICONDUCTOR EQUIPMENT SALES
Worldwide Market Share



Source: VLSI Research Inc. November 1992

SEMATECH

TOP 10 SEMICONDUCTOR EQUIPMENT SUPPLIERS WORLDWIDE SALES ($M)

1979		1992	
Fairchild	111.4	Applied Materials	794
Perkin Elmer	101.2	Tokyo Electron	677
Applied Materials	54.1	Nikon	501
GCA	54.1	Canon	333
Teradyne	53.4	Advantest	327
Varian	50.8	Teradyne	278
Tektronix	39.2	Varian	263
Eaton	37.7	Hitachi	258
Kulicke & Soffa	37.0	General Signal	231
Balzers AG	33.7	SVG	203
		ASM International	203
Total	**$572.6M**	**Total**	**$4,068M**

Source: VLSI Research Inc. 1992 estimates are preliminary.

SEMATECH

SEMATECH SUCCESS

"SEMATECH appears to be on schedule for achieving by the end of 1992 its overall objective of demonstrating the capability to manufacture state-of-the-art semiconductors using only U.S. Equipment"

> "SEMATECH's Technological Progress and Proposed R&D Program"
> General Accounting Office
> July 1992

"SEMATECH has demonstrated that a government-industry R&D consortium ... can help improve a U.S. industry's technological position while protecting the government's interest that the consortium be managed well and public funds spent appropriately."

> "Lessons Learned from SEMATECH"
> General Accounting Office
> September 1992

SEMATECH

We are currently purchasing an additional $150 million of American equipment and materials that -- without SEMATECH's revitalization of the infrastructure -- would have gone to foreign countries.

Craig Barrett
Executive Vice President
Intel Corp.

Before SEMATECH, our buying decision for the Motorola MOS 11 fabrication facility in Austin, Texas, included 75% foreign tools. Today, the MOS 11 tool set is 80% American-made equipment.

Tommy George
Senior Vice President
Motorola, Inc.

SEMATECH

SEMATECH MISSION

Create fundamental change in manufacturing technology and the domestic infrastructure to provide U.S. semiconductor companies the continuing capability to be world-class suppliers.

SEMATECH OBJECTIVES

1. Provide unit processes and generic manufacturing methods for members to integrate into their proprietary process flows and products.

2. Ensure that there is a viable supplier infrastructure capable of meeting the members' requirements for key equipment modules, materials and manufacturing systems.

3. Reduce sensitivity of cost to manufacturing volume.

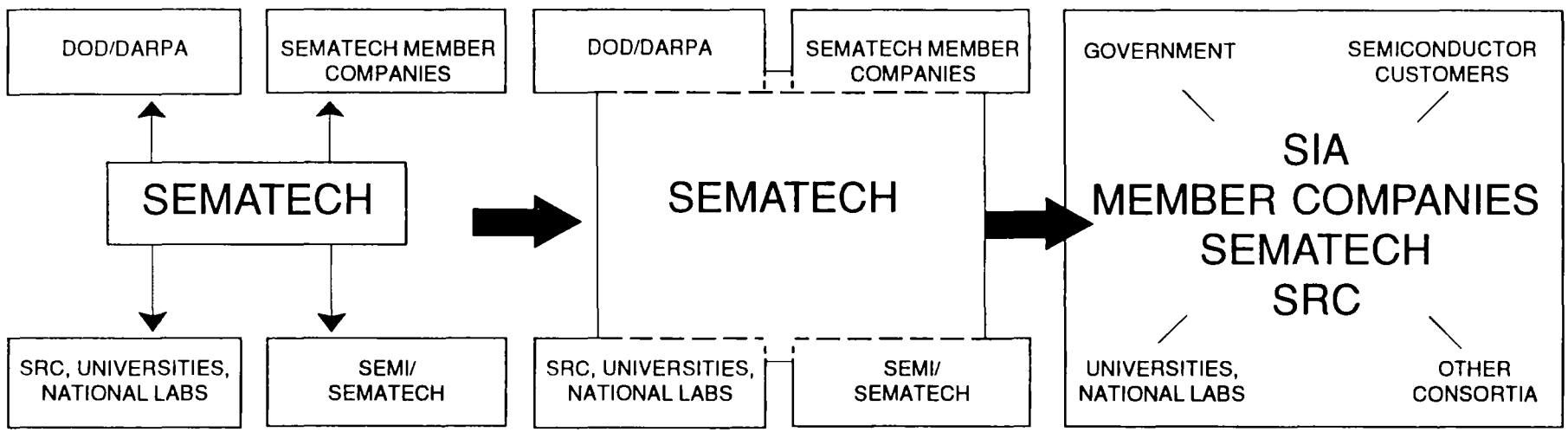
4. Provide programmable factory systems capable of responding to process changes with first pass success.

5. Cooperate with the SRC, DARPA, and national labs to develop a research and educational infrastructure necessary to sustain U.S. leadership in semiconductor technology.

6. Maintain open forums for effective communications, collaboration, and consensus building within the SEMATECH community.

SEMATECH

THE EVOLUTION OF SEMATECH



INITIAL VISION

- Members and Suppliers at arm's length
- Assignees represent companies
- Problems viewed as technical

PRESENT STATE

- Most Members and Suppliers now partnering
- Higher quality assignees dedicated to SEMATECH mission
- Problems viewed as technical, cultural, managerial and business

GOAL

- One unified national effort
  - Insuring world leadership in the semiconductor industry
  - Enabling economic competitiveness and National security

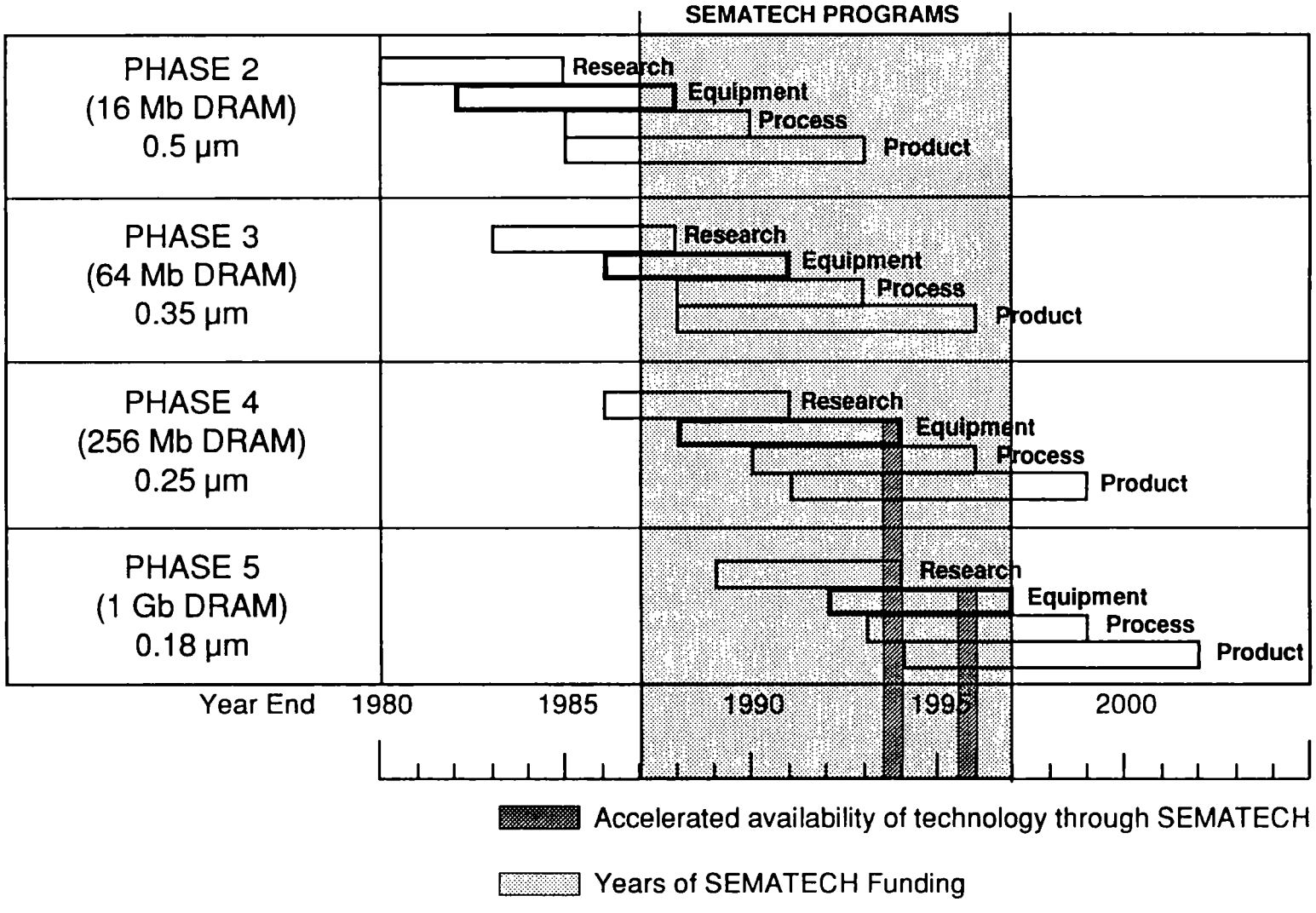
SEMATECH

SEMICONDUCTOR MANUFACTURING TRENDS

Geometries	.5μ	0.35μ	0.25μ	0.18μ
DRAM Density	16M	64M	256M	1G
DRAM Die Size (in peak year)	84mm^2	128mm^2	205mm^2	358mm^2
Equipment Buy Decision	1988	1991	1994	1997
Wafer Size	150mm	200mm	200mm	300mm
Mask Levels	10-15	15-20	20-25	25-30
Processing Steps	60-90	90-120	120-150	150-180
Fab Costs (20K wafers/month)	$360M	$550M	$900M	$1.8B

SEMATECH

TECHNOLOGY DEVELOPMENT CYCLES



SEMATECH

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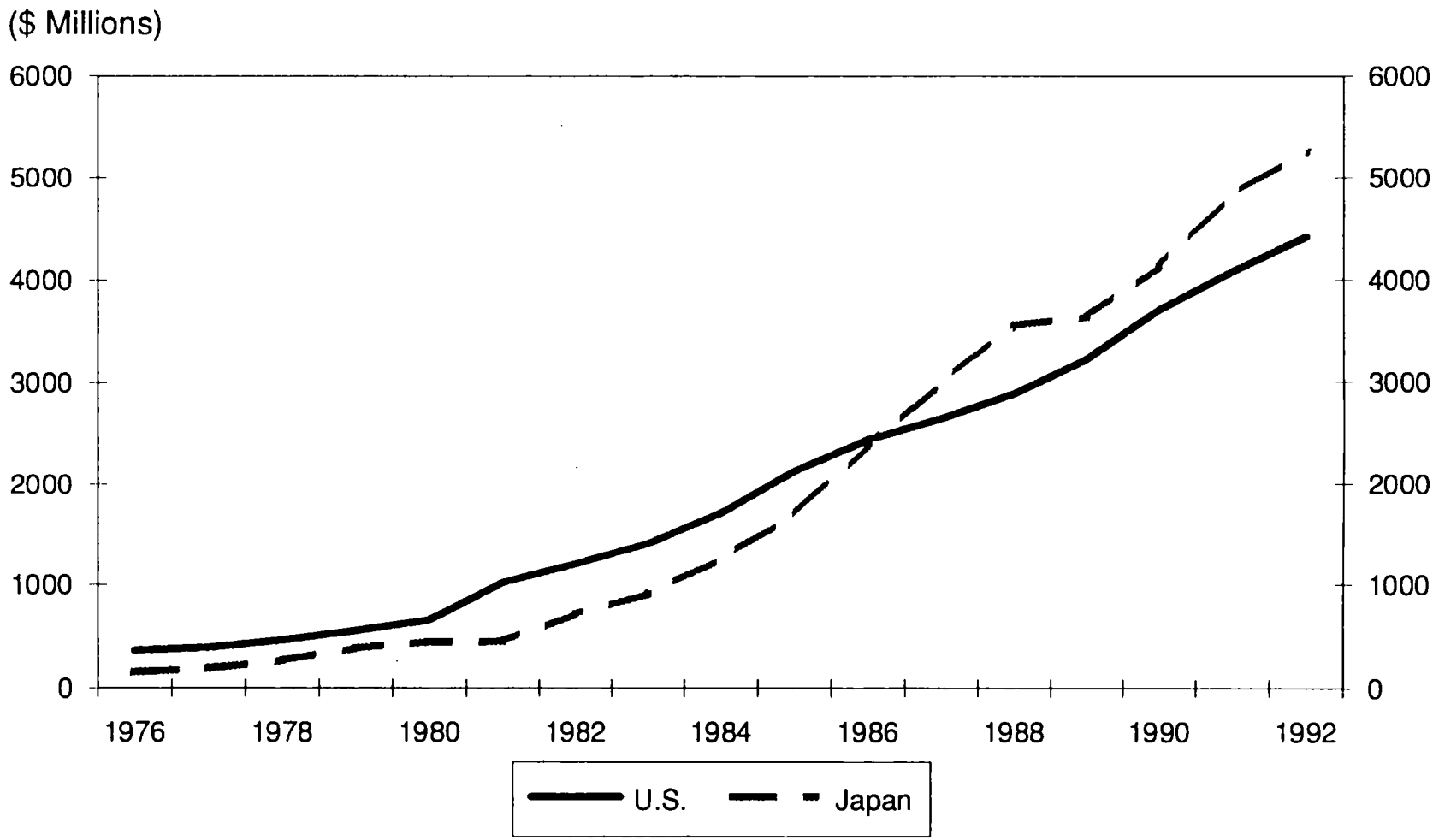
SEMICONDUCTOR R&D:
U.S. vs. JAPANESE COMPANIES

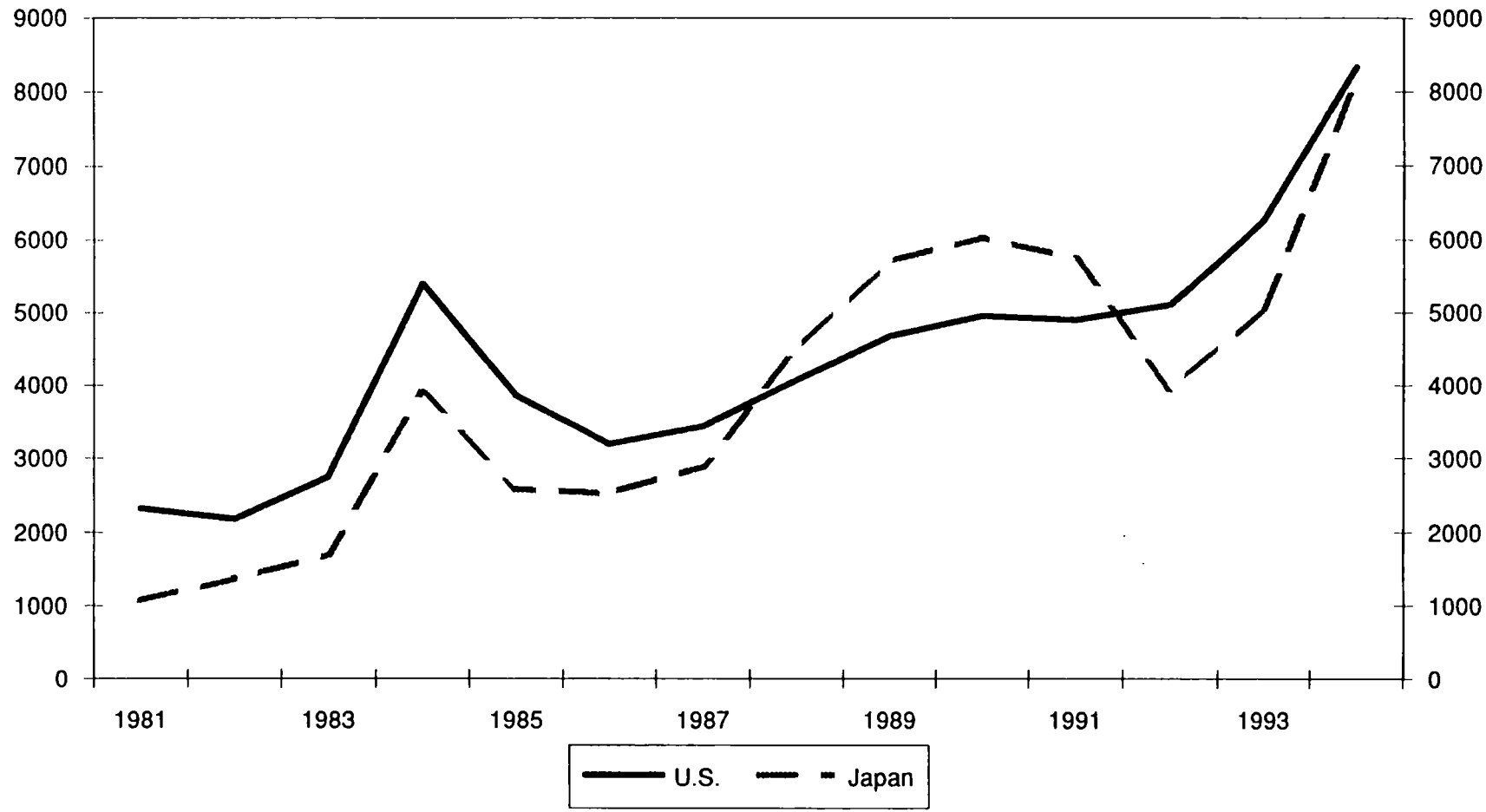


Source: 1981-1992 U.S. and 1984-1992 Japanese data from Dataquest; other years from SEMATECH sources

SEMATECH

SEMICONDUCTOR CAPITAL EXPENDITURES: U.S. vs. JAPANESE COMPANIES

($ Millions)



Source: VLSI Research Inc.

SEMATECH

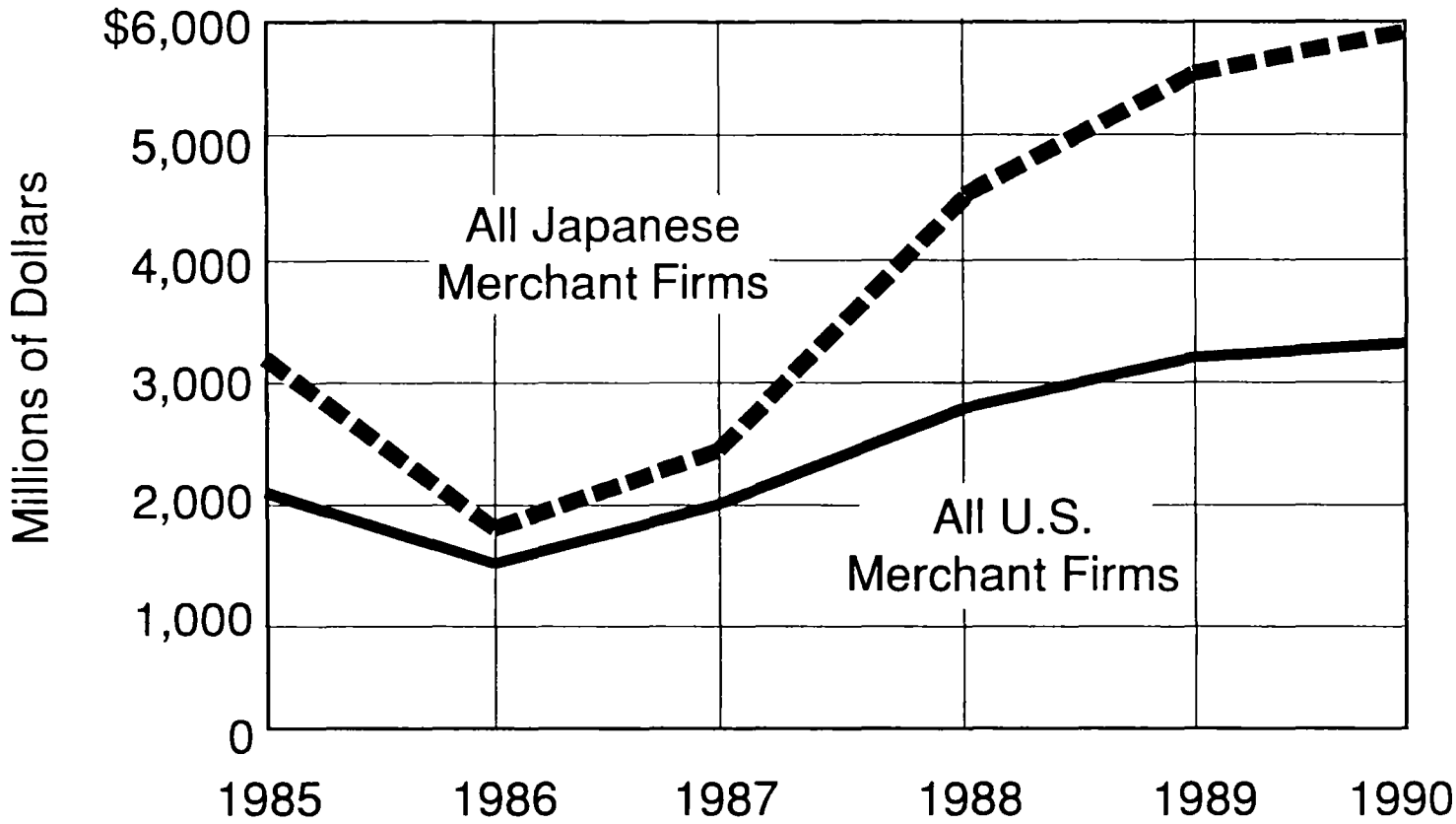
JAPANESE WORLD MATERIALS MARKET SHARE

Year	1975	1985	1988	1989	1990
All Fabrication Materials (including sputter targets, silicon wafers, chemicals, gases, and photoresists)	16%	41%	52%	56%	57%
All Packaging Materials (including ceramic packages, leadframes, and bonding wires)	35%	63%	72%	71%	75%

Source: Rose Associates and NACS, February, 1992

SEMATECH

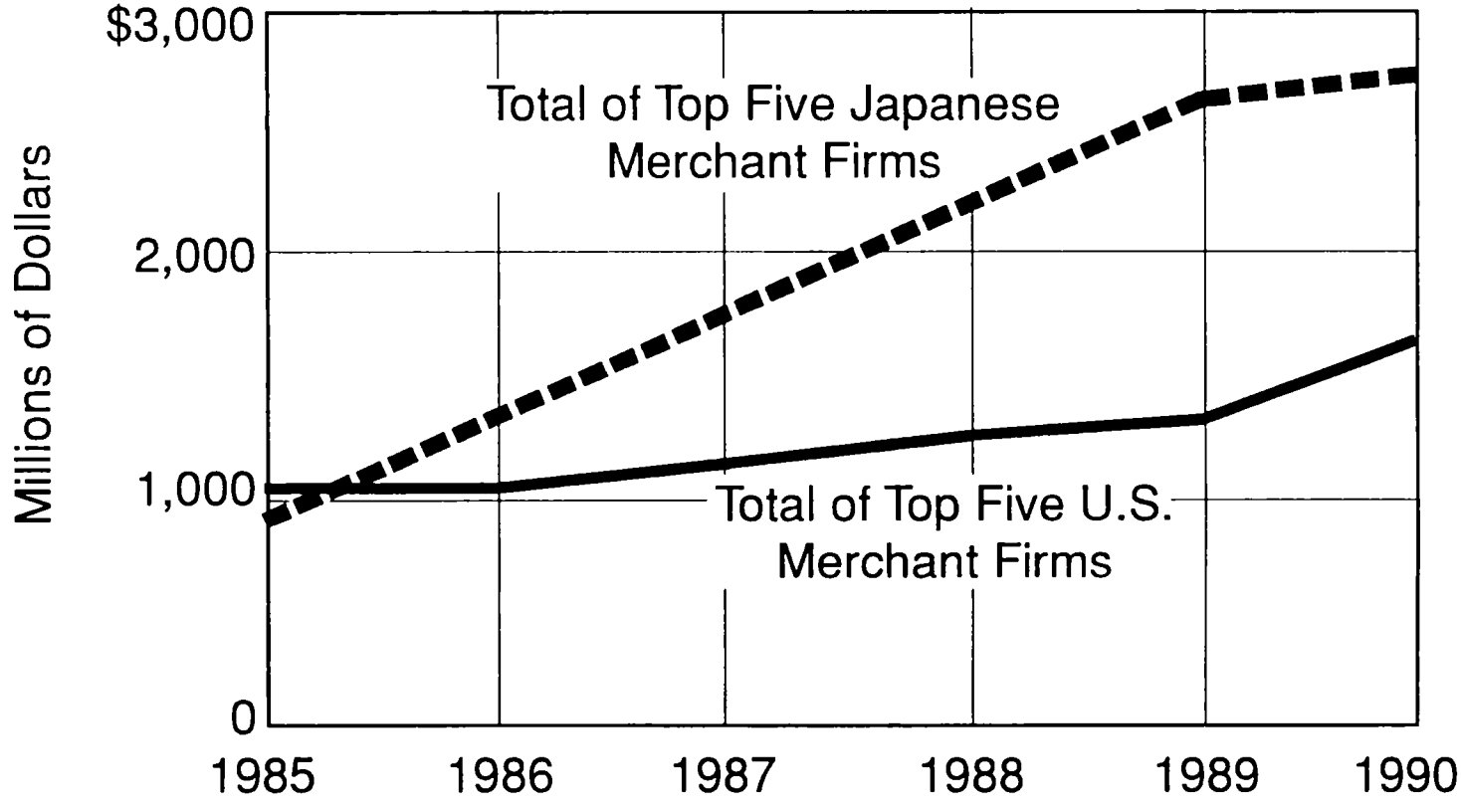
SEMICONDUCTOR CAPITAL SPENDING



Source: Dataquest and NACS, February 1992

SEMATECH

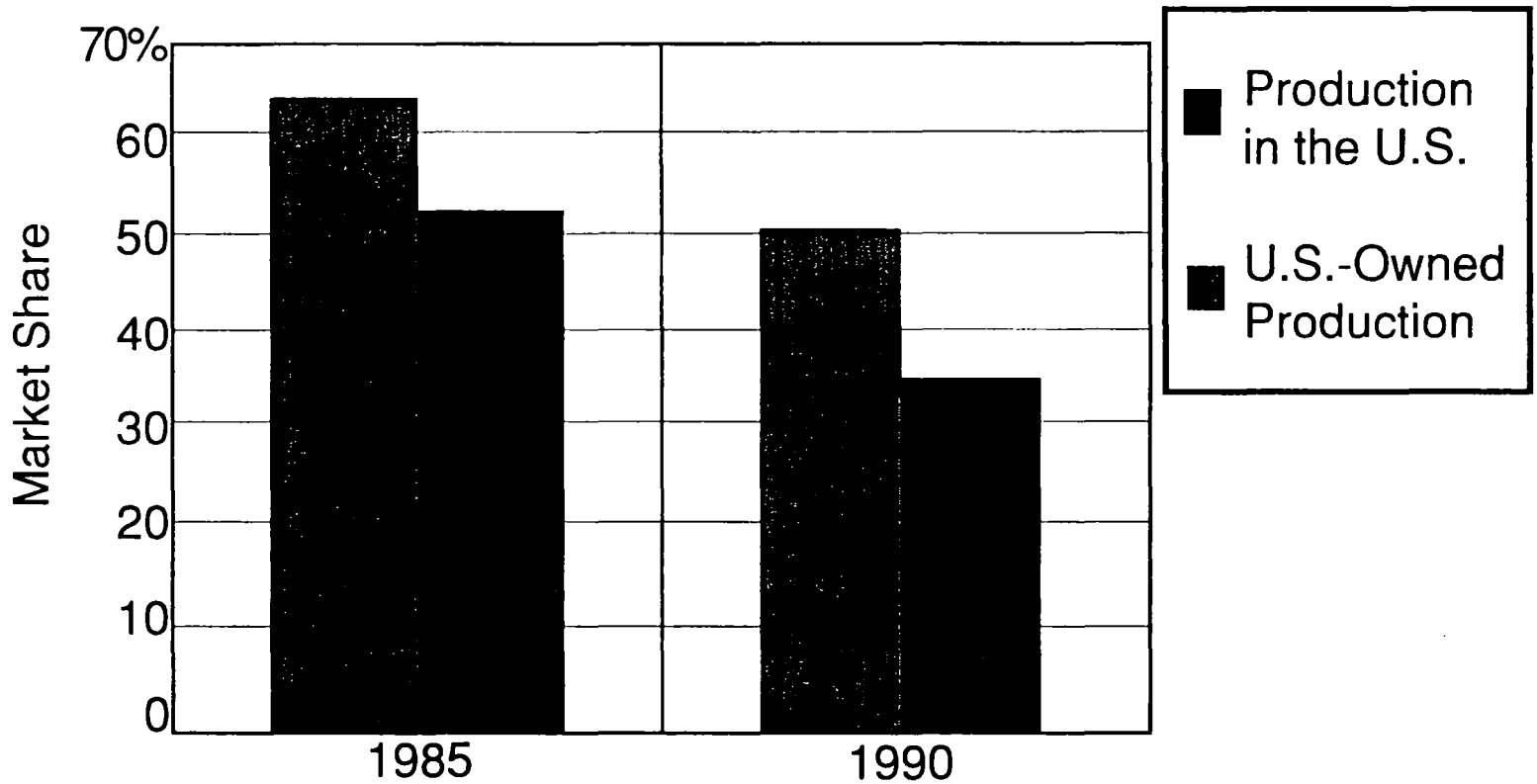
SEMICONDUCTOR R&D SPENDING



Source: Dataquest and NACS, February 1992

SEMATECH

U.S. WORLD MARKET SHARE IN ELECTRONIC PRODUCTS



Source: American Electronics Association and NACS, February, 1992

SEMATECH

SEMATECH MEASURABLE CRITERIA

0.25μm design rules by year-end 1994; 0.18μm by year-end 1996.
(Total equipment set available to leading-edge companies)

Hold Cost-of-Ownership ($/cm^2) constant at current levels ($4/cm^2 @ 25,000 wafers/mo.)

Reduce sensitivity of Cost-of-Ownership to factory capacity
(Penalty for 10X less capacity to drop from 50% to 25%)

Reduce time to field new generations of manufacturing technology by 25%

Elevate U.S. manufacturing procedures, systems, modeling and simulation to world-class levels
(measure by benchmarked criteria)

Routine achievement of specs on first pass for process variations within fab envelope

Drive suppliers to provide open, distributed factory systems, embedded equipment controllers and automated material handling systems as scheduled

At least one qualified, viable domestic supplier for each element

Continue as a forum for open communication

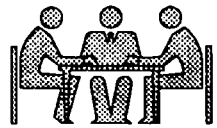
Nurture collaborative centers of manufacturing science

SEMATECH

HOW ARE WE GOING TO ACHIEVE SEMATECH'S GOALS?

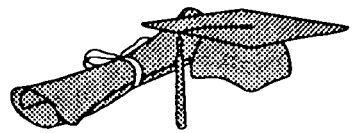
Design factory from top-down

Increase early collaboration with supplier base

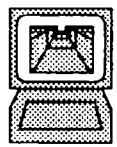


Align and leverage national programs

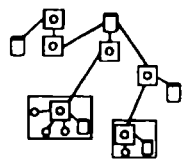
Increase collaboration with national labs and universities



Emphasize Modeling & Simulation



Focus on Manufacturing Systems



Support SIA technology roadmap goals

SEMATECH

SEMATECH - OVERALL AGENDA

- Control events vs. controlled by events
- Re-emphasize manufacturing methods through fostering information exchange among experts and formalizing methods projects through the MDL
- Foster development of modeling and simulation tools for equipment, processes and factories; drive program from top-down factory perspective
- Use modeling and simulation tools to reduce time and cost for new generations
- Help the infrastructure lower costs, reduce risk, and add value to their products
- Be a focal point for cooperation among member companies, national labs, DARPA and the national programs
- Continue to provide a forum for open communication
- Promote and implement Total Quality Management

SEMATECH

LESSONS FOR THE FUTURE

SEMATECH OVERVIEW

Build on successes
Create new types of competitive advantages/change the rules
Clearly define metrics for each objectives
Provide suppliers the capability to sustain leadership
Top-down program perspective

DARPA/SEMATECH PARTNERSHIP

Better leverage DARPA programs
Proactive role in DOD strategy
Increased DOD participation in SEMATECH programs
Full-time DOD technical transfer staff

SEMATECH

LESSONS FOR THE FUTURE

SCOPE

Continue involvement in four thrust areas

Contamination Free Manufacturing thrust area

Modeling and Simulation thrust area

Shift emphasis to building distinct competitive advantages

Control systems to enable flexibility, robustness

Manufacturing systems to include automated material handling

Increase focus on generic manufacturing methods

SEMATECH

LESSONS FOR THE FUTURE

EXECUTION

Share best practices among members
Leverage outside resources through contracts
Focal point for external cooperation
Define and utilize long-range roadmaps in all major areas

COOPERATION

Focus on technologies important to majority of members
Customer partnering program
Continue fostering environment for open communication

TECHNOLOGY TRANSFER

Tech transfer starts with early member company buy-in
Tech transfer does not end until members are using the results

SEMATECH

SOME CONDITIONS FOR SUCCESSFUL CONSORTIA

Champions are Essential

Should Represent an Entire Industry

Requires a Clear Mission
- Precompetitive
- Industry Led

Long-term Support

Member Companies Internal Support

Focus on Major National Issues

Must Attract Best People
- Essential Career Step

Measurable Success Criteria

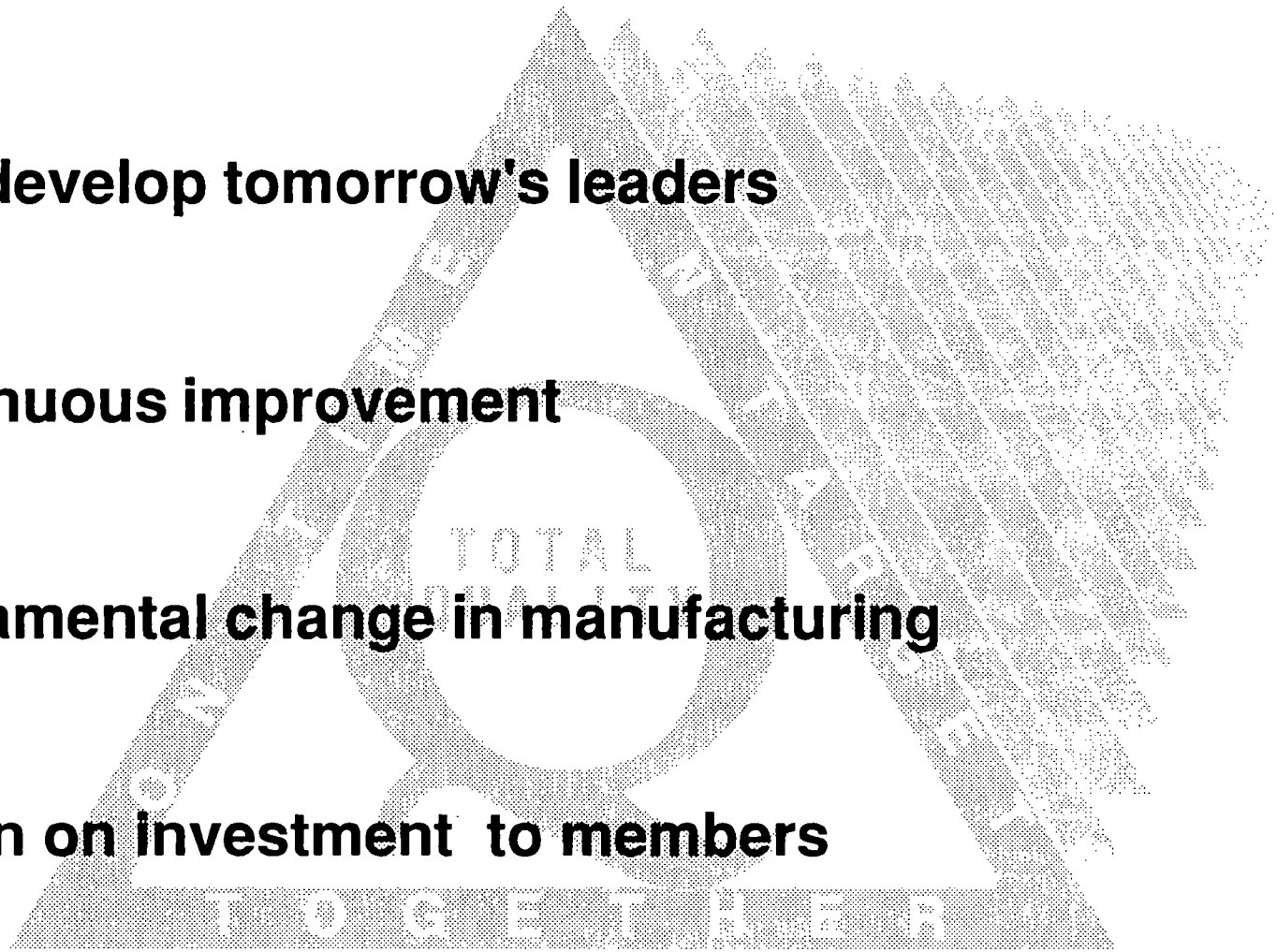
SEMATECH

WHAT I WOULD DO DIFFERENTLY AT SEMATECH

- Identify key leaders earlier
- Clearly define the mission and goals
- Select four or five technical specialists
- Don't build a 6,000 M^2 cleanroom
- Establish long-term funding with measurable goals
- Take equity for equipment investments

SEMATECH

SEMATECH CRITERIA FOR SUCCESS



Help develop tomorrow's leaders

Continuous improvement

Fundamental change in manufacturing

Return on investment to members

SEMATECH

SUMMARY

1. SEMATECH has been an experiment in industry-government cooperation that has worked

2. U.S. equipment companies and semiconductor manufacturers are better off today with SEMATECH than they were five years ago

3. The U.S. should learn from SEMATECH's experiences and avoid our steep learning curve

4. SEMATECH will have a role in America's technology base well into the 21st Century

5. "On Target, On-Time, Together"

SEMATECH

SEMICONDUCTOR EQUIPMENT SALES DEMOGRAPHICS

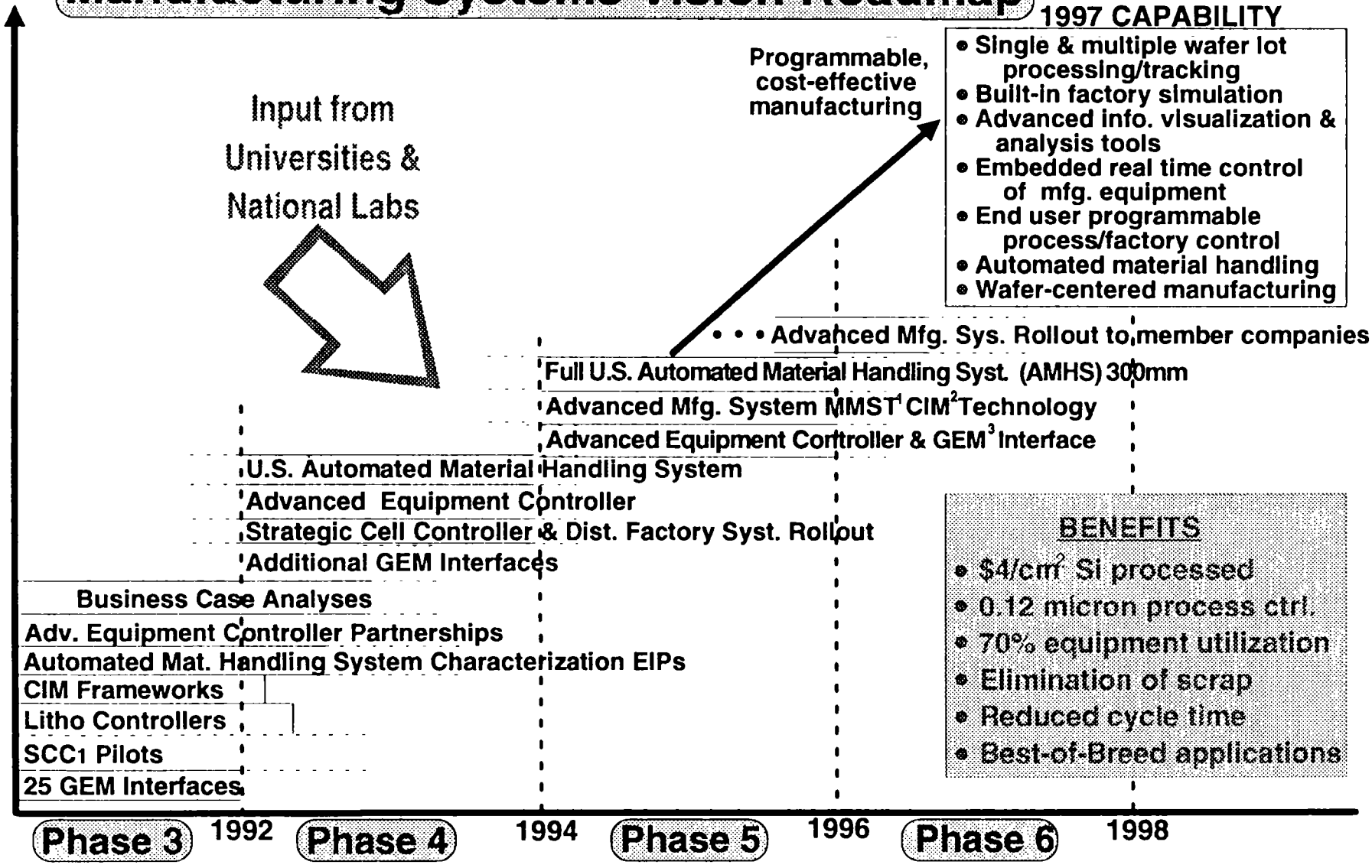
Purchase and Market Share in Percent

	1987	1988	1989	1990	1991	1992E		1997F	1991 Preliminary
United States Purchase Share	48.8	35.6	34.2	33.4	33.3	33.9	...	36.5	35.4
US Share	82.6	83.1	81.0	76.6	79.4	82.7	...	86.2	78.9
Japan Share	13.7	13.0	15.4	19.4	14.6	13.6	...	11.6	18.4
ROW Share	3.7	3.9	3.7	4.1	6.0	3.8	...	2.2	2.6
Japan Purchase Share	36.3	41.6	40.8	42.7	42.3	41.0	...	40.2	39.3
US Share	21.9	20.1	17.6	14.9	19.2	20.6	...	21.8	17.0
Japan Share	76.7	78.8	81.6	83.9	79.3	78.6	...	78.0	82.4
ROW Share	1.4	1.1	0.8	1.2	1.5	0.8	...	0.1	0.6
ROW Purchase Share	14.9	22.8	25.0	23.9	24.4	25.0	...	23.4	25.2
US Share	57.2	55.5	51.7	49.9	49.9	49.1	...	46.8	49.3
Japan Share	20.1	20.3	21.0	22.3	26.7	25.5	...	29.6	32.0
ROW Share	22.6	24.3	27.3	27.8	23.4	25.4	...	23.6	18.7
Total World Purchase Share	100.0	100.0	100.0	100.0	100.0	100.0	...	100.0	100.0
US Share	56.8	50.6	47.8	43.9	46.7	48.8	...	51.1	47.1
Japan Share	37.5	42.0	43.8	47.6	44.9	43.2	...	42.5	47.0
ROW Share	5.7	7.4	8.4	8.5	8.3	8.0	...	6.4	5.9

Source: VLSI Research Inc.

SEMATECH

Manufacturing Systems Vision Roadmap



[1] Microelectronics Manfacturing Science & Technology
[2] Computer Integrated Manufacturing
[3] Generic Equipment Model

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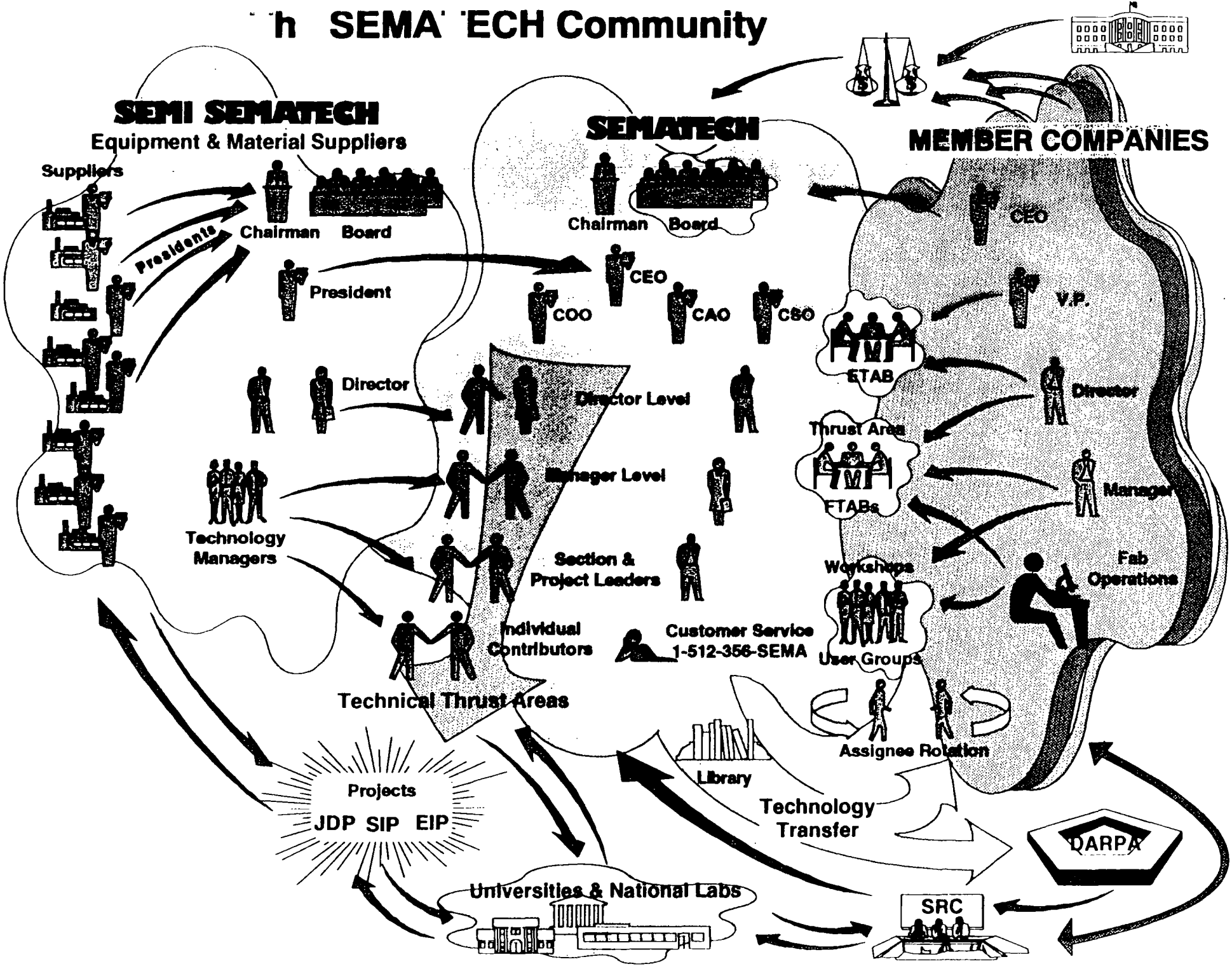
SEMATECH


h SEMA ECH Community
SEMI SEMATECH
Equipment & Material Suppliers
Suppliers
Presidents
Chairman
Board
President
Director
Technology Managers
SEMATECH
Chairman
Board
CEO
COO
CAO
CSO
Director Level
Manager Level
Section & Project Leaders
Individual Contributors
Technical Thrust Areas
Customer Service 1-512-356-SEMA
MEMBER COMPANIES
CEO
V.P.
ETAB
Director
Thrust Area
FTABs
Manager
Workshops
User Groups
Fab Operations
Assignee Rotation
Library
Technology Transfer
Projects
JDP SIP EIP
Universities & National Labs
SRC
DARPA

SEMATECH BOARD OF DIRECTORS MEETING

- **New mission statement developed**
  Solve technical challenges required to keep the U.S. number one in the global semiconductor industry

- **Meet Phase 4 goals on time and within budget**

- **Continue focus on domestic core tools and technologies required for world-class semiconductor manufacturing**

- **Broadened charter**
  Include entire spectrum of SIA Roadmaps, for example ...
  - Packaging
  - Test
  - Design
  - Materials

- **Work within the SIA framework to define a national strategy for lithography**

- **Work within the SIA framework to influence the spending and resource allocations at federal labs**

- **1993 budget at full $200M 1:1 matching:**
  1994 budget at $180M as recommended by SEMATECH OCE

SEMATECH

FACTORS LEADING TO SEMATECH'S EXPANDED MISSION

- Growing complexity of ICs is driving up packaging, materials, test costs and fab costs
- Packaging and test have become critical cost factors in IC manufacturing
- Packaging and test each may cost more than the chip itself
- U.S. materials companies hold less than 10% share of the world market
- SEMATECH's current scope includes less than half the total cost factors in producing ICs
- SEMATECH's success at convening the industry should be extended to non-wafer fab IC activities

SEMATECH

IMPLICATIONS ON LONG-RANGE PLAN

- 1994-99 spending at $150M-$200M/year
- 30-50% of project funding to new areas

  Packaging
  Design
  National lithography strategy
  Test
  Materials

- Strong focus on timely commercialization of technology
- All spending exclusive of

  Larger wafer size
  Future factory realization

- SCOE funding transitioned to SRC

SEMATECH

SEMATECH
2706 Montopolis Drive, Austin, Texas 78741-6499
512-356-3500

Date Rec'd 6/14
ACTION to
INFO to JHG
Johnson
MN
MS
SIG of
Returned
Date Out

A Team of America's Best

Advanced Micro Devices, Inc.
★
American Telephone and Telegraph Company
★
Defense Advanced Research Projects Agency (DARPA)
★
Digital Equipment Corporation
★
Hewlett-Packard Company
★
Intel Corporation
★
International Business Machines Corporation
★
Motorola
★
NCR Corporation*
★
National Semiconductor Corporation
★
Rockwell International Corporation
★
Texas Instruments Incorporated

*NCR Corporation has been acquired by American Telephone and Telegraph Company.

June 4, 1993

Ms. Susana Almanza
Ms. Sylvia Ledesma
EIGNC/PODER
P.O. Box 33225
Austin, TX 78764

Dear Ms. Almanza and Ms. Ledesma:

Thank you for your letter of May 24th. I think it may be useful for the various people on the distribution list in that it may serve to focus the point on which we cannot agree.

You state that you are "...pleased with SEMATECH's timely response to the specific environmental proposals..." but that your "...concerns about SEMATECH go far beyond these environmental proposals." You go on to state the opinion that "SEMATECH must be accountable to the communities and workers directly affected by the semiconductor industry."

This is a role which we believe is not appropriate or feasible, and which we are not capable of fulfilling. Your description of SEMATECH in the same paragraph as "... a government-sponsored agency with a $100M per year taxpayer subsidy..." reflects a basic misunderstanding about our consortium, and is perhaps the source of your frustration.

The government funding we receive is not a subsidy, but rather an investment in the nation by DoD/ARPA to acquire technology and to maintain a domestic source of leading-edge microchips. The advantage to the government is that, unlike any other technology development spending, our industrial members match the DoD/ARPA dollars on a 1:1 basis and further leverage these funds by incenting additional matching by the suppliers to our Member Companies.

The Electronics Industry Good Neighbor Campaign proposal for SEMATECH is somewhat analagous to asking the U.S. Advanced Battery Consortium to be accountable for the entire automobile industry, or asking the National Center for Manufacturing Science to be solely accountable to the communities and workers in which their members are located.

It is this disconnect and the fact that your interest in SEMATECH goes far beyond environmental and local community concerns that lead me to conclude that a formal advisory relationship would not be productive. SEMATECH remains committed to meeting its objectives, and in doing so will exceed the direction contained in the Conference Committee's report language. We are also committed to the policy of being a responsible neighbor in the local community, and we have demonstrated our ability to perform on both these points.

As a result of the input from the May 22 meeting with local organizations, we will explore the feasibility of SEMATECH helping to create a new two-year degree program in the Austin area which would be more accessible to local youth and to examine possible new efforts aimed at strengthening 0-6 school/parenting programs.

We would welcome your continued participation in these areas, assuming it remains productive.

Sincerely,

Frank Squires
Senior Vice President
and Chief Administrative Officer

MFS:abd

c: U.S. Rep. J. J. Pickle
Duane Adams, Deputy Director, ARPA
William Andahazy, Staff, House Armed Services Committee
Sen. Jeff Bingaman, Senate Armed Services Committee
Carol Browner, Administrator, EPA
Marcos de Leon, Travis County Commissioner
Rep. Ron Dellums, Chair, House Armed Services Committee
Gary Denman, Director, ARPA
Dr. John Gibbons, Director, Office of Science and Technology Policy
Dr. Dan Herr, Semiconductor Research Corporation
William Perry, Deputy Secretary of Defense
Andrew Procassini, President, Semiconductor Industry Association
Robert Reich, Secretary of Labor
Sven Roosild, Deputy Director, Microelectronics Technology Office, ARPA
Rep. Patricia Schroeder, Chair, House Armed Services Subcommittee on Research and Technology

Electronics Industry Good Neighbor Campaign

a collaboration between the Campaign for Responsible Technology
and the Southwest Network for Environmental and Economic Justice

1993 Collaboration Participants

☐ TONATIERRA
P.O. Box 24009
Phoenix, AZ 85074
602-254-5230 (o & FAX)

☐ People Organized in Defense of Earth and its Resources
P.O. Box 33225
Austin, TX 78764
512-445-0036
512-445-7403 (FAX)

☐ Silicon Valley Toxics Coalition
760 North First St.
San Jose, CA 95112
408-287-6707
408-287-6771 (FAX)

☐ SouthWest Organizing Project
211 10th St., SW
Albuquerque, NM 87102
505-247-8832
505-247-9972 (FAX)

Coordinators:
Richard Moore
☐ Southwest Network for Environmental and Economic Justice
P.O. Box 7399
Albuquerque, NM 87194
505-242-0416
505-242-5609 (FAX)

Rand Wilson
☐ Campaign for Responsible Technology
408 Highland Ave.
Somerville, MA 02144
617-391-3866
617-623-5943 (FAX)

Please respond to offices checked above

May 24, 1993

Mr. Franklin Squires, Chief Administrative officer
SEMATECH
2706 Montopolis Drive
Austin, TX 78741

Dear Mr. Squires,

Members of the Campaign for Responsible Technology (CRT) and the Southwest Network for Environmental and Economic Justice have reviewed both the April 5, 1993 "Meeting Summary" prepared by SEMATECH and your May 7, 1993 response to the Electronics Industry Good Neighbor Campaign proposals.

In general, we are pleased with SEMATECH's timely response to the specific environmental proposals we submitted prior to the Dallas meeting in April. However, our concerns about SEMATECH go far beyond these environmental proposals.

As a government-sponsored agency with a $100 million per year taxpayer subsidy, SEMATECH must be accountable to the communities and workers directly affected by the semiconductor industry. As SEMATECH's role in implementing the Clinton administration's technology policy expands, it becomes even more imperative that affected workers, community organizations, and environmental and health and safety advocates be formally included in SEMATECH's policy decisions.

The detailed budget materials and specific goals and timetables we have requested are lacking in your response. We doubt that publication of another report or holding another general meeting in September will be sufficient to deal with these concerns.

That's why we view our continued participation and oversight as the most essential element in our future relationship.

Unfortunately, it appears our request to be included in a formal advisory

relationship and to have representatives involved in SEMATECH's oversight and governance has been denied. Further, our proposal to have SEMATECH assist the capacity of community-based organizations to be meaningfully involved in the process has also been denied.

The Electronics Industry Good Neighbor Campaign will formulate our future plan of action accordingly at a meeting we have planned in San Jose on June 18 and 19th.

Sincerely,

Susana Almanza

Susana Almanza, Co-Chair
PODER

Sylvia Ledesma

Sylvia Ledesma
EIGNC/PODER

cc:
Duane Adams, Deputy Director, ARPA
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